SONY

Diagonal 8.9 mm (Type 1/1.8) CMOS solid-state Image Sensor with Square Pixel for Color Cameras

IMX265LQR-C

Pregius

Description

The IMX265LQR-C is a diagonal 8.9 mm (Type 1/1.8) CMOS active pixel type solid-state image sensor with a square pixel array and 3.19 M effective pixels. This chip features a global shutter with variable charge-integration time. This chip operates with analog 3.3 V, digital 1.2 V, and interface 1.8 V triple power supply, and has low power consumption. High sensitivity, low dark current and low PLS characteristics are achieved.
(Applications: FA cameras, ITS cameras)

Features

- ◆CMOS active pixel type dots
- ◆Built-in timing adjustment circuit, H/V driver and serial communication circuit
- ◆Global shutter function
- ◆Input frequency
  37.125 MHz / 74.25 MHz / 54 MHz
- ◆Number of recommended recording pixels: 2048 (H) × 1536 (V) approx. 3.15 M pixels
  Readout mode
  All-pixel scan mode
  1080p-Full HD readout mode
  Vertical / Horizontal 1 / 2 Subsampling mode
  ROI mode
  Vertical / Horizontal - Normal / Inverted readout mode
- ◆Readout rate
  Maximum frame rate in
  All-pixel scan mode: 12 bit: 55.6 frame/s
- ◆Variable-speed shutter function (resolution 1 H units)
- ◆12-bit A/D converter
- ◆CDS / PGA function
  0 dB to 24 dB: Analog Gain (0.1 dB step)
  24.1 dB to 48 dB: Analog Gain: 24 dB + Digital Gain: 0.1 dB to 24 dB (0.1 dB step)
- ◆I/O interface
  Low voltage LVDS (150 mVp-p) serial (4 ch) DDR output
- ◆Recommended lens F number: 2.8 or more (Close side)
- ◆Recommended exit pupil distance: –100 mm to –∞

Exmor

E15X06A5X

Device Structure

- CMOS image sensor
- Image size
  Diagonal 8.9 mm (Type 1/1.8) Approx. 3.19 M pixels All-pixel
  Diagonal 7.7 mm (Type 1/2.35) Approx. 2.11 M pixels 1080p-Full HD
- Total number of pixels
  2064 (H) × 1554 (V) Approx. 3.21 M pixels
- Number of effective pixels
  2064 (H) × 1544 (V) Approx. 3.19 M pixels
- Number of active pixels
  2064 (H) × 1544 (V) Approx. 3.19 M pixels
- Number of recommended recording pixels
  2048 (H) × 1536 (V) Approx. 3.15 M pixels All-pixel
  1920 (H) × 1080 (V) Approx. 2.07 M pixels 1080p-Full HD
- Unit cell size
  3.45 µm (H) × 3.45 µm (V)
- Optical black
  Horizontal (H) direction: Front 0 pixels, rear 0 pixels
  Vertical (V) direction: Front 10 pixels, rear 0 pixels
- Substrate material
  Silicon

Absolute Maximum Ratings

Item	Symbol	Rating			Unit	Remarks
Supply voltage (Analog 3.3 V)	AV_{DD}	–0.3	to	+4.0	V	
Supply voltage (Interface 1.8 V)	OV_{DD}	–0.3	to	+3.3	V	
Supply voltage (Digital 1.2 V)	DV_{DD}	–0.3	to	+2.0	V	
Input voltage	VI	–0.3	to	OV_{DD} +0.3	V	Not exceed 3.3 V
Output voltage	VO	–0.3	to	OV_{DD} +0.3	V	Not exceed 3.3 V
Operating temperature	Topr	-30	to	+75	˚C	
Storage temperature	Tstg	-40	to	+85	˚C	
Performance guarantee temperature	Tspec	-10	to	+60	˚C	

Recommended Operating Conditions

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage (Analog 3.3 V)	AV_{DD}	3.15	3.30	3.45	V
Supply voltage (Interface 1.8 V)	OV_{DD}	1.70	1.80	1.90	V
Supply voltage (Digital 1.2 V)	DV_{DD}	1.10	1.20	1.30	V

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General-0.0.8

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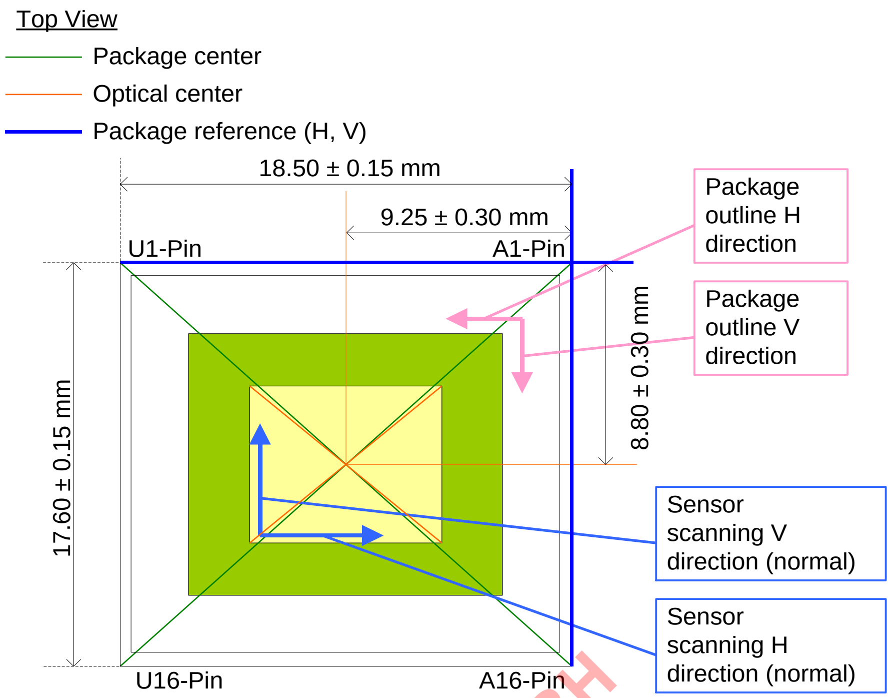
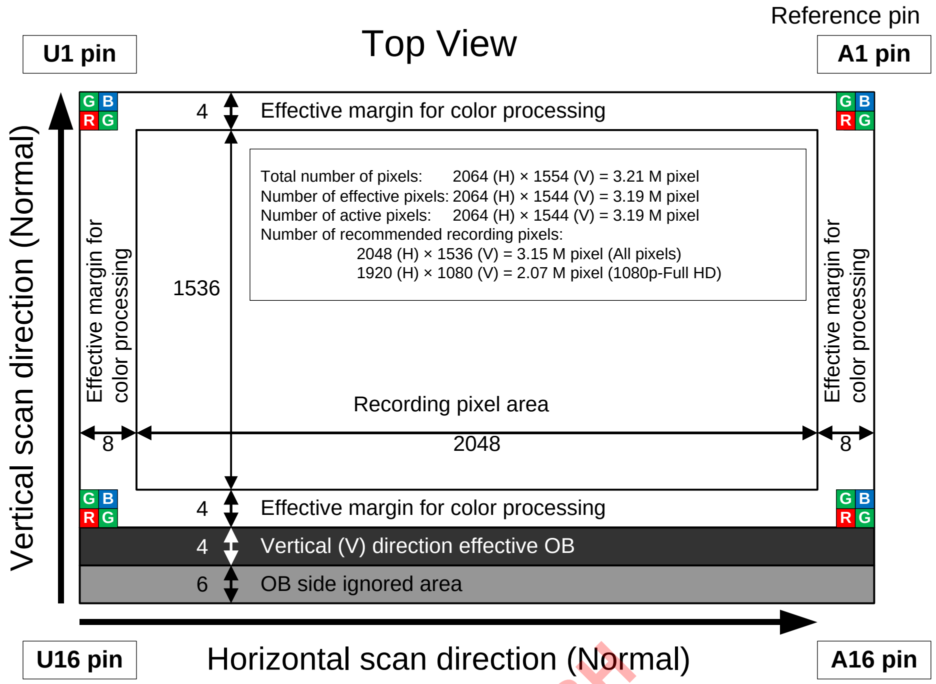
Chip Center and Optical Center



Optical Center

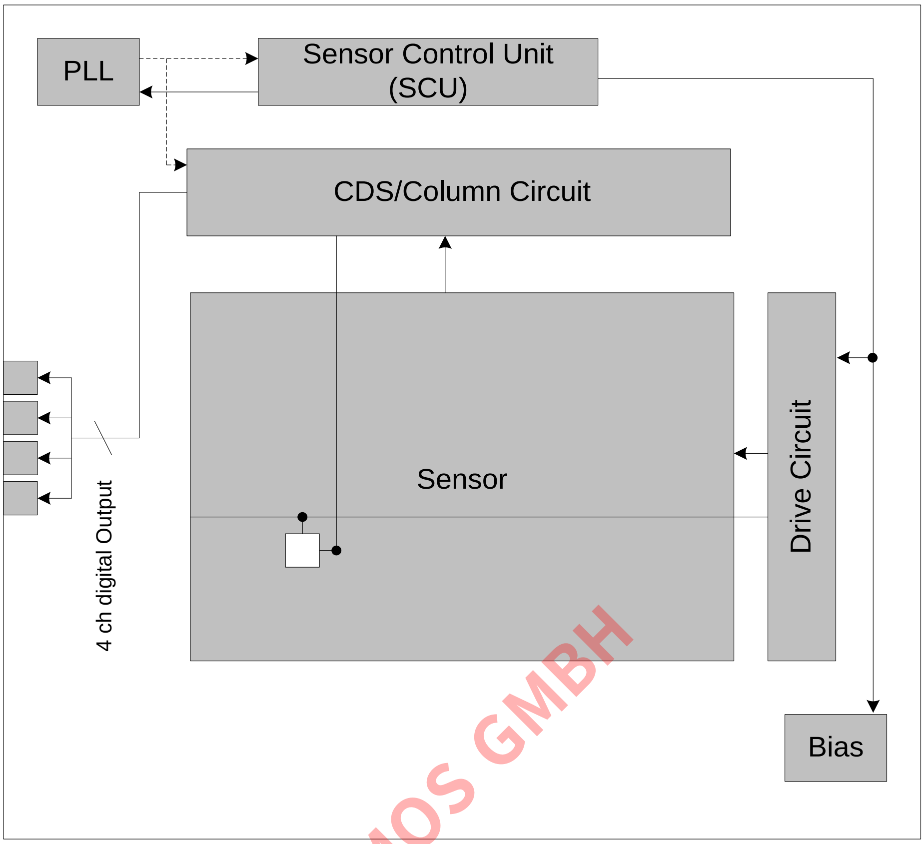
Pixel Arrangement



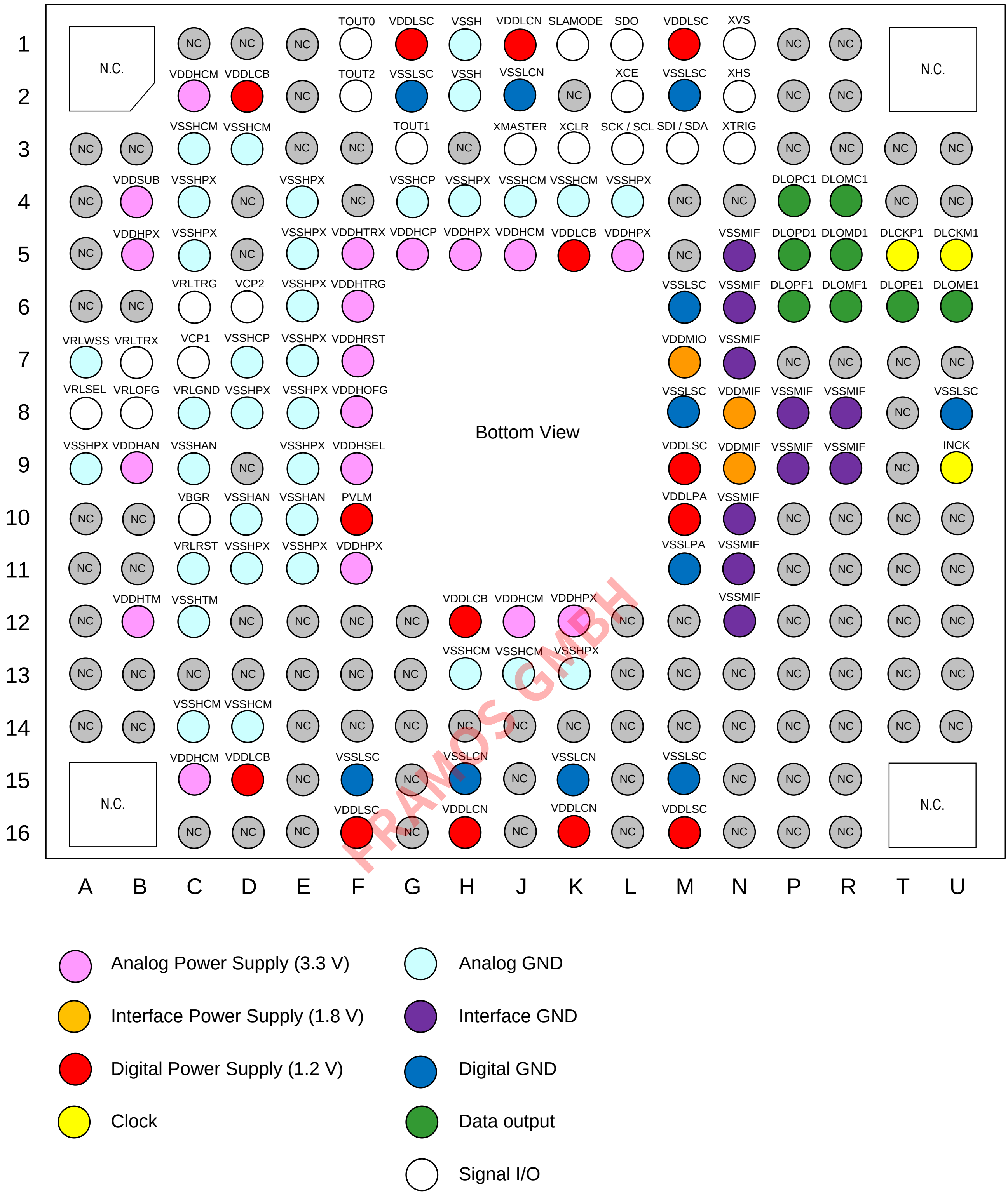
Pixel Arrangement

Block Diagram and Pin Configuration

(Top View)



Block Diagram



Pin Configuration

Pin Description

No.	Pin No.	I/O	Analog / Digital	Symbol	Description
1	A1	—	—	N.C.	—
2	A3	—	—	N.C.	—
3	A4	—	—	N.C.	—
4	A5	—	—	N.C.	—
5	A6	—	—	N.C.	—
6	A7	GND	A	VRLWSS	3.3V GND
7	A8	I	A	VRLSEL	Connect to VCP1
8	A9	GND	A	VSSHPX	3.3V GND
9	A10	—	—	N.C.	—
10	A11	—	—	N.C.	—
11	A12	—	—	N.C.	—
12	A13	—	—	N.C.	—
13	A14	—	—	N.C.	—
14	A16	—	—	N.C.	—
15	B3	—	—	N.C.	—
16	B4	Power	A	VDDSUB	3.3V power supply
17	B5	Power	A	VDDHPX	3.3V power supply
18	B6	—	—	N.C.	—
19	B7	I	A	VRLTRX	Connect to VCP1
20	B8	I	A	VRLOFG	Connect to VCP1
21	B9	Power	A	VDDHAN	3.3V power supply
22	B10	—	—	N.C.	—
23	B11	—	—	N.C.	—
24	B12	Power	A	VDDHTM	3.3V power supply
25	B13	—	—	N.C.	—
26	B14	—	—	N.C.	—
27	C1	—	—	N.C.	—
28	C2	Power	A	VDDHCM	3.3V power supply
29	C3	GND	A	VSSHCM	3.3V GND
30	C4	GND	A	VSSHPX	3.3V GND
31	C5	GND	A	VSSHPX	3.3V GND
32	C6	I	A	VRLTRG	Connect to VCP2
33	C7	O	A	VCP1	Connect to VRLSEL, VRLTRX, VRLOFG (Connect to 4.7 µF × 2 to GND)
34	C8	GND	A	VRLGND	3.3V GND
35	C9	GND	A	VSSHAN	3.3V GND
36	C10	O	A	VBGR	Connect to 0.22 µF to GND
37	C11	GND	A	VRLRST	3.3V GND
38	C12	GND	A	VSSHTM	3.3V GND
39	C13	—	—	N.C.	—
40	C14	GND	A	VSSHCM	3.3V GND
41	C15	Power	A	VDDHCM	3.3V power supply
42	C16	—	—	N.C.	—
43	D1	—	—	N.C.	—
44	D2	Power	A	VDDLCB	1.2V power supply
45	D3	GND	A	VSSHCM	3.3V GND
46	D4	—	—	N.C.	—
47	D5	—	—	N.C.	—
48	D6	O	A	VCP2	Connect to VRLTRG (Connect to 4.7 µF × 2 to GND)
49	D7	GND	A	VSSHCP	3.3V GND
50	D8	GND	A	VSSHPX	3.3V GND
51	D9	—	—	N.C.	—
52	D10	GND	A	VSSHAN	3.3V GND
53	D11	GND	A	VSSHPX	3.3V GND
54	D12	—	—	N.C.	—
55	D13	—	—	N.C.	—
56	D14	GND	A	VSSHCM	3.3V GND
57	D15	Power	A	VDDLCB	1.2V power supply
58	D16	—	—	N.C.	—
59	E1	—	—	N.C.	—
60	E2	—	—	N.C.	—
61	E3	—	—	N.C.	—

No.	Pin No.	I/O	Analog / Digital	Symbol	Description
62	E4	GND	A	VSSHPX	3.3V GND
63	E5	GND	A	VSSHPX	3.3V GND
64	E6	GND	A	VSSHPX	3.3V GND
65	E7	GND	A	VSSHPX	3.3V GND
66	E8	GND	A	VSSHPX	3.3V GND
67	E9	GND	A	VSSHPX	3.3V GND
68	E10	GND	A	VSSHAN	3.3V GND
69	E11	GND	A	VSSHPX	3.3V GND
70	E12	—	—	N.C.	—
71	E13	—	—	N.C.	—
72	E14	—	—	N.C.	—
73	E15	—	—	N.C.	—
74	E16	—	—	N.C.	—
75	F1	O	D	TOUT0	Pulse0 output pin
76	F2	O	D	TOUT2	Pulse2 output pin
77	F3	—	—	N.C.	—
78	F4	—	—	N.C.	—
79	F5	Power	A	VDDHTRX	3.3V power supply
80	F6	Power	A	VDDHTRG	3.3V power supply
81	F7	Power	A	VDDHRST	3.3V power supply
82	F8	Power	A	VDDHOFG	3.3V power supply
83	F9	Power	A	VDDHSEL	3.3V power supply
84	F10	Power	A	PVLM	1.2V power supply
85	F11	Power	A	VDDHPX	3.3V power supply
86	F12	—	—	N.C.	—
87	F13	—	—	N.C.	—
88	F14	—	—	N.C.	—
89	F15	GND	D	VSSLSC	1.2V GND
90	F16	Power	D	VDDLSC	1.2V power supply
91	G1	Power	D	VDDLSC	1.2V power supply
92	G2	GND	D	VSSLSC	1.2V GND
93	G3	O	D	TOUT1	Pulse1 output pin
94	G4	GND	A	VSSHCP	3.3V GND
95	G5	Power	A	VDDHCP	3.3V power supply
96	G12	—	—	N.C.	—
97	G13	—	—	N.C.	—
98	G14	—	—	N.C.	—
99	G15	—	—	N.C.	—
100	G16	—	—	N.C.	—
101	H1	GND	D	VSSH	3.3V GND
102	H2	GND	D	VSSH	3.3V GND
103	H3	—	—	N.C.	—
104	H4	GND	A	VSSHPX	3.3V GND
105	H5	Power	A	VDDHPX	3.3V power supply
106	H12	Power	A	VDDLCB	1.2V power supply
107	H13	GND	A	VSSHCM	3.3V GND
108	H14	—	—	N.C.	—
109	H15	GND	D	VSSLCN	1.2V GND
110	H16	Power	D	VDDLCN	1.2V power supply
111	J1	Power	D	VDDLCN	1.2V power supply
112	J2	GND	D	VSSLCN	1.2V GND
113	J3	I	D	XMASTER	Master / Slave select (Slave Mode: High, Master Mode: Low)
114	J4	GND	A	VSSHCM	3.3V GND
115	J5	Power	A	VDDHCM	3.3V power supply
116	J12	Power	A	VDDHCM	3.3V power supply
117	J13	GND	A	VSSHCM	3.3V GND
118	J14	—	—	N.C.	—
119	J15	—	—	N.C.	—
120	J16	—	—	N.C.	—
121	K1	I	D	SLAMODE	Slave address select (1A : High, 10: Low)
122	K2	—	—	N.C.	—
123	K3	I	D	XCLR	System clear (Normal: High, Clear: Low)
124	K4	GND	A	VSSHCM	3.3V GND
125	K5	Power	A	VDDLCB	1.2V power supply

No.	Pin No.	I/O	Analog / Digital	Symbol	Description
126	K12	Power	A	VDDHPX	3.3V power supply
127	K13	GND	A	VSSHPX	3.3V GND
128	K14	—	—	N.C.	—
129	K15	GND	D	VSSLCN	1.2V GND
130	K16	Power	D	VDDLCN	1.2V power supply
131	L1	O	D	SDO	4-wire: Serial communication I/F SDO pin I^{2}C: OPEN
132	L2	I	D	XCE	4-wire: Serial communication I/F XCE pin I^{2}C: Fixed to High
133	L3	I	D	SCK / SCL	4-wire: Serial communication I/F SCK pin I^{2}C: Serial clock line
134	L4	GND	A	VSSHPX	3.3V GND
135	L5	Power	A	VDDHPX	3.3V power supply
136	L12	—	—	N.C.	—
137	L13	—	—	N.C.	—
138	L14	—	—	N.C.	—
139	L15	—	—	N.C.	—
140	L16	—	—	N.C.	—
141	M1	Power	D	VDDLSC	1.2V power supply
142	M2	GND	D	VSSLSC	1.2V GND
143	M3	I/O	D	SDI / SDA	4-wire: Serial communication I/F SDI pin I^{2}C: Serial data line
144	M4	—	—	N.C.	—
145	M5	—	—	N.C.	—
146	M6	GND	D	VSSLSC	1.2V GND
147	M7	Power	D	VDDMIO	1.8V power supply
148	M8	GND	D	VSSLSC	1.2V GND
149	M9	Power	D	VDDLSC	1.2V power supply
150	M10	Power	D	VDDLPA	1.2V power supply
151	M11	GND	D	VSSLPA	1.2V GND
152	M12	—	—	N.C.	—
153	M13	—	—	N.C.	—
154	M14	—	—	N.C.	—
155	M15	GND	D	VSSLSC	1.2V GND
156	M16	Power	D	VDDLSC	1.2V power supply
157	N1	I/O	D	XVS	Vertical sync signal
158	N2	I/O	D	XHS	Horizontal sync signal
159	N3	I	D	XTRIG	Trigger input
160	N4	—	—	N.C.	—
161	N5	GND	D	VSSMIF	1.8V GND
162	N6	GND	D	VSSMIF	1.8V GND
163	N7	GND	D	VSSMIF	1.8V GND
164	N8	Power	D	VDDMIF	1.8V power supply
165	N9	Power	D	VDDMIF	1.8V power supply
166	N10	GND	D	VSSMIF	1.8V GND
167	N11	GND	D	VSSMIF	1.8V GND
168	N12	GND	D	VSSMIF	1.8V GND
169	N13	—	—	N.C.	—
170	N14	—	—	N.C.	—
171	N15	—	—	N.C.	—
172	N16	—	—	N.C.	—
173	P1	—	—	N.C.	—
174	P2	—	—	N.C.	—
175	P3	—	—	N.C.	—
176	P4	O	D	DLOPC1	Low Voltage LVDS serial output (Data)
177	P5	O	D	DLOPD1	Low Voltage LVDS serial output (Data)
178	P6	O	D	DLOPF1	Low Voltage LVDS serial output (Data)
179	P7	—	—	N.C.	—
180	P8	GND	D	VSSMIF	1.8V GND
181	P9	GND	D	VSSMIF	1.8V GND
182	P10	—	—	N.C.	—
183	P11	—	—	N.C.	—
184	P12	—	—	N.C.	—
185	P13	—	—	N.C.	—
186	P14	—	—	N.C.	—

No.	Pin No.	I/O	Analog / Digital	Symbol	Description
187	P15	—	—	N.C.	—
188	P16	—	—	N.C.	—
189	R1	—	—	N.C.	—
190	R2	—	—	N.C.	—
191	R3	—	—	N.C.	—
192	R4	O	D	DLOMC1	Low Voltage LVDS serial output (Data)
193	R5	O	D	DLOMD1	Low Voltage LVDS serial output (Data)
194	R6	O	D	DLOMF1	Low Voltage LVDS serial output (Data)
195	R7	—	—	N.C.	—
196	R8	GND	D	VSSMIF	1.8V GND
197	R9	GND	D	VSSMIF	1.8V GND
198	R10	—	—	N.C.	—
199	R11	—	—	N.C.	—
200	R12	—	—	N.C.	—
201	R13	—	—	N.C.	—
202	R14	—	—	N.C.	—
203	R15	—	—	N.C.	—
204	R16	—	—	N.C.	—
205	T3	—	—	N.C.	—
206	T4	—	—	N.C.	—
207	T5	O	D	DLCKP1	Low Voltage LVDS serial output (Clock)
208	T6	O	D	DLOPE1	Low Voltage LVDS serial output (Data)
209	T7	—	—	N.C.	—
210	T8	—	—	N.C.	—
211	T9	—	—	N.C.	—
212	T10	—	—	N.C.	—
213	T11	—	—	N.C.	—
214	T12	—	—	N.C.	—
215	T13	—	—	N.C.	—
216	T14	—	—	N.C.	—
217	U1	—	—	N.C.	—
218	U3	—	—	N.C.	—
219	U4	—	—	N.C.	—
220	U5	O	D	DLCKM1	Low Voltage LVDS serial output (Clock)
221	U6	O	D	DLOME1	Low Voltage LVDS serial output (Data)
222	U7	—	—	N.C.	—
223	U8	GND	D	VSSLSC	1.2V GND
224	U9	I	D	INCK	Master clock input
225	U10	—	—	N.C.	—
226	U11	—	—	N.C.	—
227	U12	—	—	N.C.	—
228	U13	—	—	N.C.	—
229	U14	—	—	N.C.	—
230	U16	—	—	N.C.	—

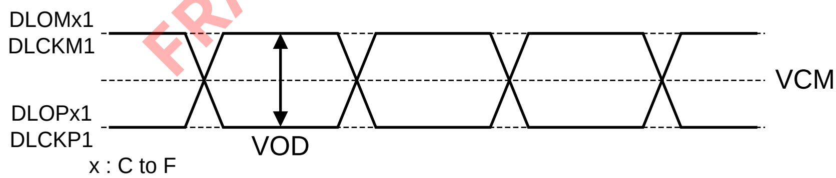
* N.C. pins in the table above should be left open on the board.

Electrical Characteristics

DC Characteristics

Item		Pins	Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply voltage	Analog	$V_{DD}Hx$	AV_{DD}	—	3.15	3.30	3.45	V
	Interface	$V_{DD}Mx$	OV_{DD}	—	1.70	1.80	1.90	V
	Digital	$V_{DD}Lx$	DV_{DD}	—	1.10	1.20	1.30	V
Digital input voltage		XHS XVS XCLR INCK XMASTER SLAMODE SCK SDI XCE XTRIG	VIH	XVS / XHS in Slave mode	0.8 × OV_{DD}	—	—	V
			VIL		—	—	0.2 × OV_{DD}	V
Digital output voltage		DLOPx1 DLOMx1 DCKP1 DCKM1 x: C to F	VCM	Low voltage LVDS (termination resistance: 100 Ω)	—	$OV_{DD}/2$	—	mV
			VOD		100	150	210	mV
		XHS XVS SDO TOUT1 TOUT2	VOH	XVS / XHS in Master mode	OV_{DD} -0.4	—	—	V
			VOL		—	—	0.4	V

LVDS output



Power Consumption

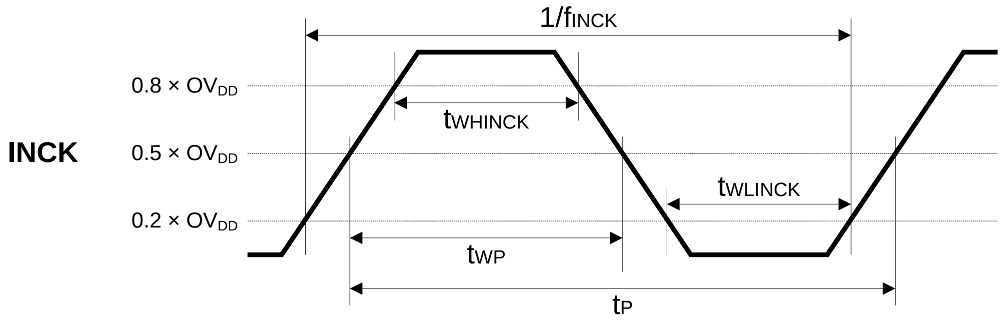
Item	Pins	Symbol	Typ.	Max.	Unit
Operating current Serial LVDS 4 ch 12 bit 55.6 frame/s	$V_{DD}H$	IAV_{DD}	120	175	mA
	$V_{DD}M$	IOV_{DD}	11	20	mA
	$V_{DD}L$	IDV_{DD}	120	180	mA
Standby current	$V_{DD}H$	IAV_{DD}_STB	—	0.5	mA
	$V_{DD}M$	IOV_{DD}_STB	—	0.5	mA
	$V_{DD}L$	IDV_{DD}_STB	—	20	mA

Operating current:
(Typical value condition) : Supply voltage: 3.30 V / 1.80 V / 1.20 V, Tj = 25 ˚C
(Maximum value condition) : Supply voltage: 3.45 V / 1.90 V / 1.30 V, Tj = 60 ˚C
Worst state of internal circuit operating current consumption.

Standby current:
(Maximum value condition) : Supply voltage: 3.45 V / 1.90 V / 1.30 V, Tj = 60 ˚C, INCK = 0 V,
The device in the light-obstructed state.

AC Characteristics

Master Clock (INCK) Waveform Diagram

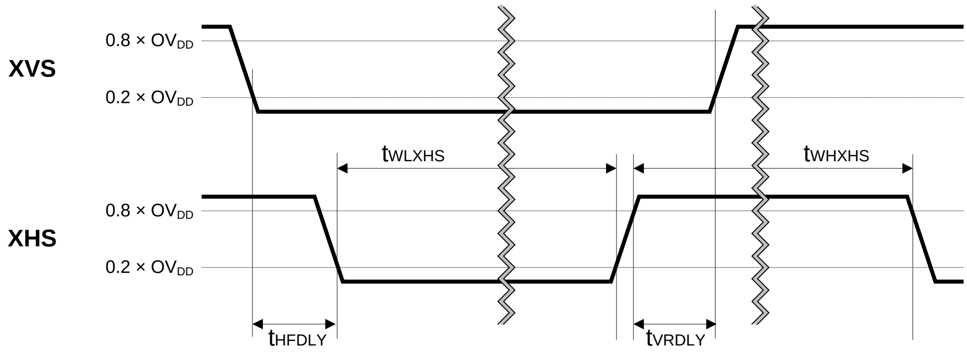


Duty Ratio = t_{WP} / t_P × 100

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
INCK clock frequency	f_{INCK}	f_{INCK} × 0.96	f_{INCK}	f_{INCK} × 1.02	MHz	f_{INCK} = 37.125 MHz, 74.25 MHz, 54 MHz
INCK Low level pulse width	t_{WLINCK}	4	—	—	ns	
INCK High level pulse width	t_{WHINCK}	4	—	—	ns	
INCK clock duty	—	45.0	50.0	55.0	%	Define with 0.5 × OV_{DD}

* The INCK fluctuation affects the frame rate.

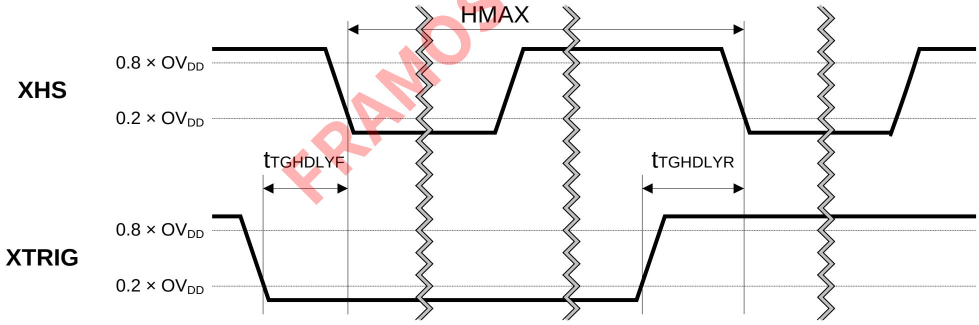
XVS / XHS Input Characteristics in Slave Mode (XMASTER = High)



Item	Symbol	Min.	Typ.	Max.	Unit
XHS Low level pulse width	t_{WLXHS}	$4/f_{INCK}$	—	—	ns
XHS High level pulse width	t_{WHXHS}	$4/f_{INCK}$	—	—	ns
XVS - XHS fall width	t_{HFDLY}	$1/f_{INCK}$	—	—	ns
XHS - XVS rise width	t_{VRDLY}	$1/f_{INCK}$	—	—	ns

Synchronization cannot be performed from XVS and XHS signal in mater mode. Detect the sync code.

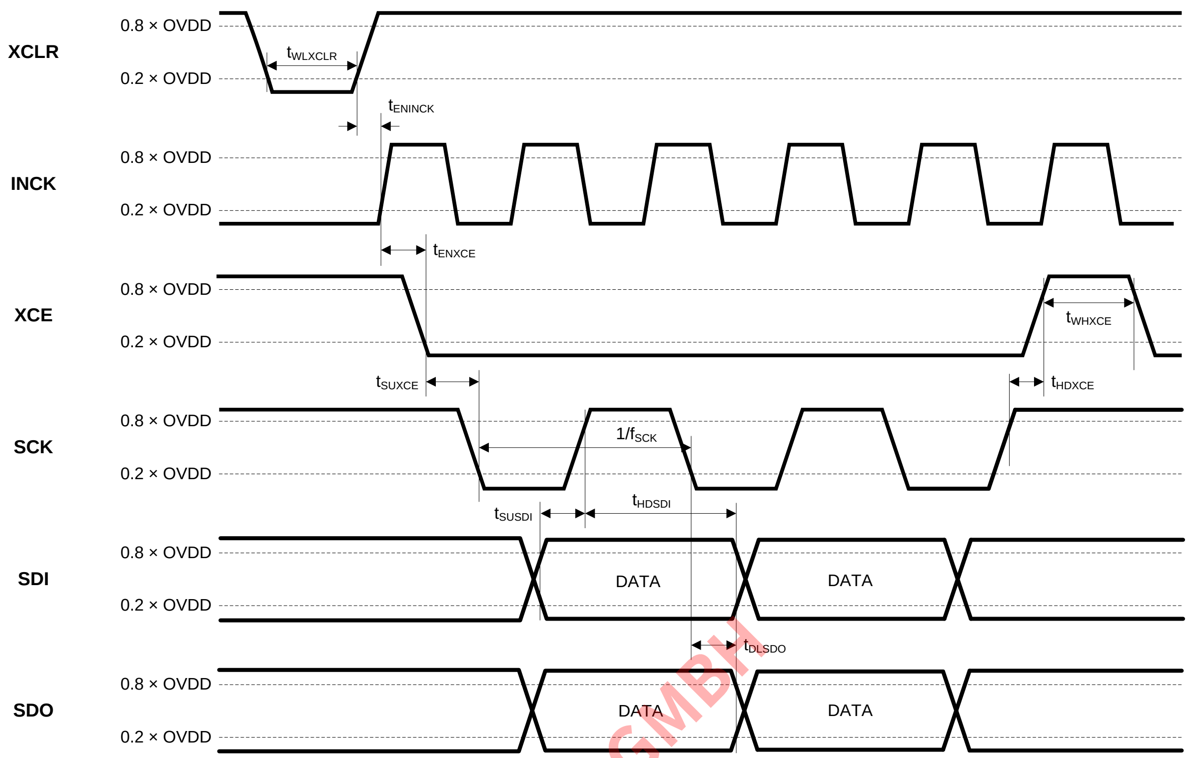
XTRIG Input Characteristics in Slave Mode (XMASTER = High) only



Item	Symbol	Min.	Typ.	Max.	Unit
XTRIG fall - XHS fall width	$t_{TGHDLYF}$	10	—	HMAX-10	INCK
XTRIG rise - XHS fall width	$t_{TGHDLYR}$	10	—	HMAX-10	INCK

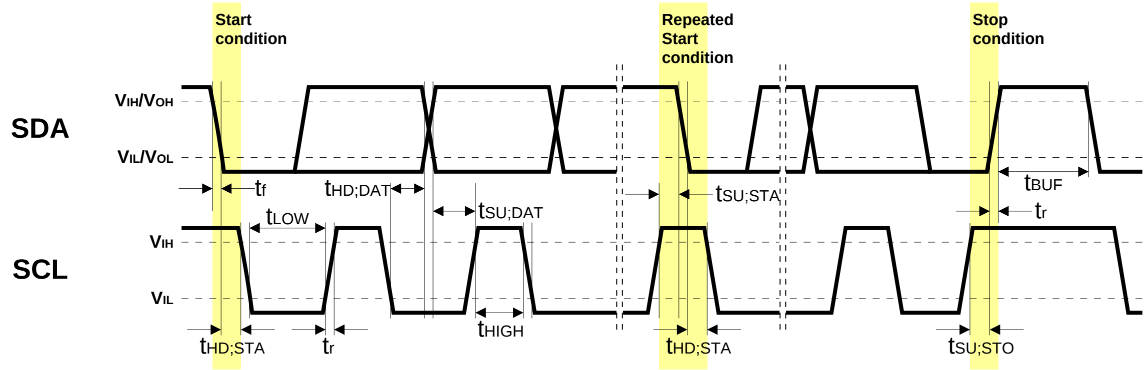
Serial Communication

4-wire



Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
SCK clock frequency	f_{SCK}	—	—	13.5	MHz	
XCLR Low level pulse width	t_{WLXCLR}	$4/f_{INCK}$	—	—	ns	
INCK effective margin	t_{ENINCK}	1	—	—	µs	
XCE effective margin	t_{ENXCE}	20	—	—	µs	
XCE input setup time	t_{SUXCE}	20	—	—	ns	
XCE input hold time	t_{HDXCE}	20	—	—	ns	
XCE High level pulse width	t_{WHXCE}	20	—	—	ns	
SDI input setup time	t_{SUSDI}	10	—	—	ns	
SDI input hold time	t_{HDSDI}	10	—	—	ns	
SDO output delay time	t_{DLSDO}	0	—	25	ns	Output load capacitance: 20 pF

I^2C



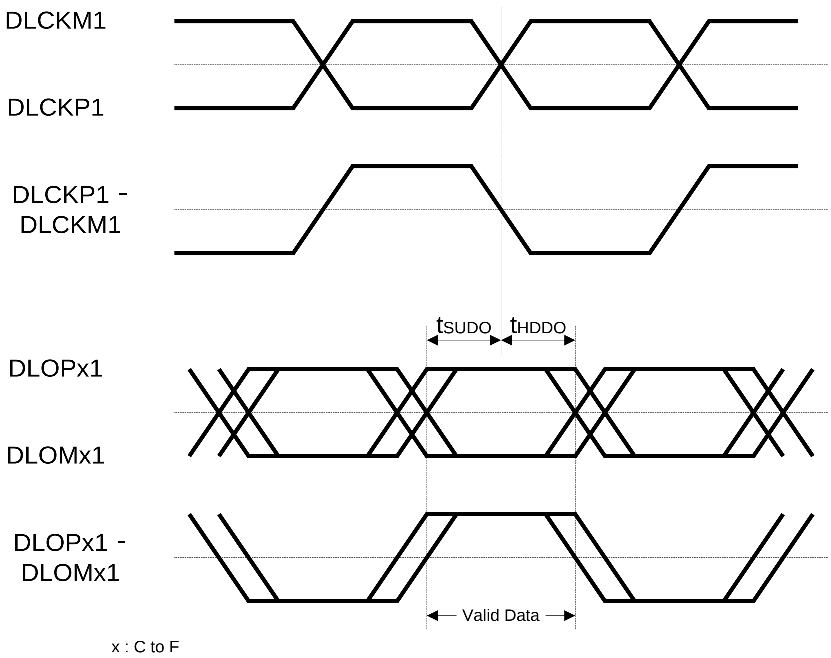
I^2C Specification

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
Low level input voltage	V_{IL}	-0.3	—	$0.3 \times OV_{DD}$	V	
High level input voltage	V_{IH}	$0.7 \times OV_{DD}$	—	1.9	V	
Low level output voltage	V_{OL}	0	—	$0.2 \times OV_{DD}$	V	$OV_{DD} < 2$ V, Sink 3 mA
High level output voltage	V_{OH}	$0.8 \times OV_{DD}$	—	—	V	
Output fall time	tof	—	—	250	ns	Load 10 pF – 400 pF, $0.7 \times OV_{DD} – 0.3 \times OV_{DD}$
Input current	Ii	-10	—	10	µA	$0.1 \times OV_{DD} – 0.9 \times OV_{DD}$
Capacitance for SCK (/SCL) , SDI (/SDA)	Ci	—	—	10	pF	

I^2C AC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
SCL clock frequency	f_{SCL}	0	—	400	kHz
Hold time (Start Condition)	t_{HDSTA}	0.6	—	—	µs
Low period of the SCL clock	t_{LOW}	1.3	—	—	µs
High period of the SCL clock	t_{HIGH}	0.6	—	—	µs
Set-up time (Repeated Start Condition)	t_{SUSTA}	0.6	—	—	µs
Data hold time	t_{HDDAT}	0	—	0.9	µs
Data set-up time	t_{SUDAT}	100	—	—	ns
Rise time of both SDA and SCL signals	t_R	—	—	300	ns
Fall time of both SDA and SCL signals	t_F	—	—	300	ns
Set-up time (Stop Condition)	t_{SUSTO}	0.6	—	—	µs
Bus free time between a Stop and Start Condition	t_{BUF}	1.3	—	—	µs

DLCKP1 / DLCKM1, DLOPx1 / DLOMx1

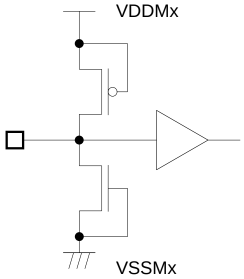
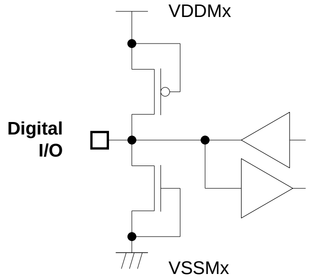
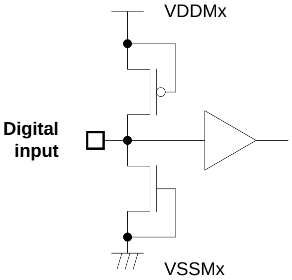
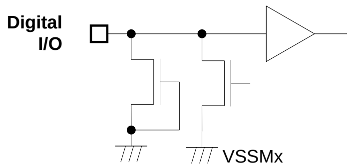
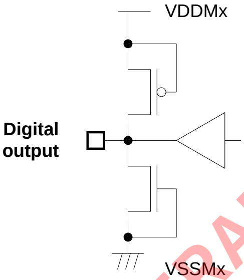
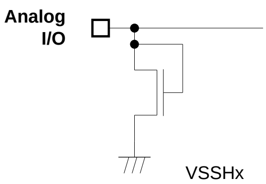
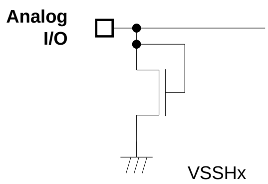
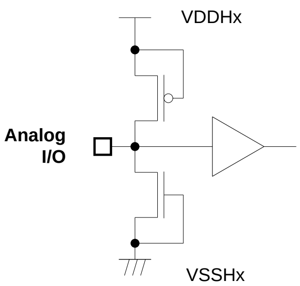
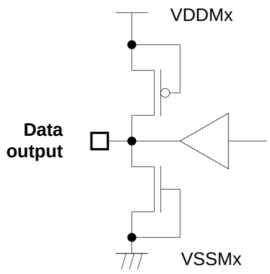


(Output load capacitance: 8 pF)

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
DLCK clock duty	—	40	50	60	%	DCK freq = 297 MHz (Max.)
DLO setup time	t_{SUDO}	400	—	—	ps	Data Rate 297 MHz DDR
DLO hold time	t_{HDDO}	400	—	—	ps	Data Rate 297 MHz DDR

I/O Equivalent Circuit Diagram

□ : External pin

Symbol	Equivalent circuit	Symbol	Equivalent circuit
INCK		XVS XHS	
XCLR XCE XMASTER XTRIG SLAMODE		SDI / SDA SCK / SCL	
SDO			
VCP1 VCP2		VRLOFG VRLTRX VRLSEL VRLTRG	
VBGR		DLOPx1 DLOMx1 DCKP1 DCKM1 x : C to F	

Spectral Sensitivity Characteristics

(Excludes lens characteristics and light source characteristics.)

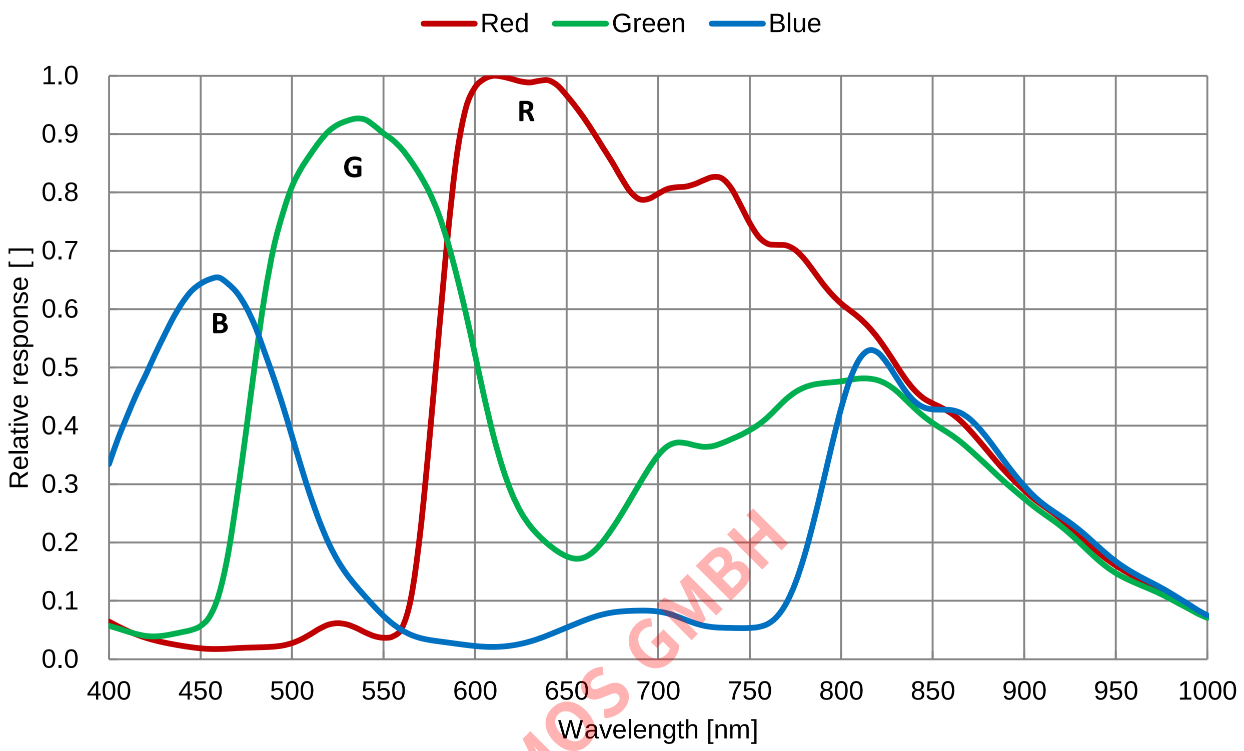


Image Sensor Characteristics

(AV_{DD} = 3.3 V, OV_{DD} = 1.8 V, DV_{DD} = 1.2 V, All-pixel scan mode, AD: 12 bit, Tj = 60 ˚C, Gain = 0 dB)

Item		Symbol	Min.	Typ.	Max.	Unit	Measurement method	Remarks
Sensitivity		S	3967 (970)	4687 (1146)	—	Digit (mV)	1	1/30 s storage
Sensitivitiy rati	RG	RG	0.47	—	0.62	—	2	
	BR	BG	0.29	—	0.44	—		
Saturation signal		Vsat2D	4094 (1001 *1)	—	—	Digit (mV)	3	Zone 0 to II'
Video signal shading		SH01	—	—	20	%	4	Zone 0, I
		SH2D	—	—	25	%		Zone 0 to II'
Dark signal		Vdt	—	—	0.61 (0.15)	Digit (mV)	5	1/30 s storage
Dark signal shading		ΔVdt	—	—	1.02 (0.25)	Digit (mV)	6	1/30 s storage
PLS (Parasitic Light Sensitivity)		Sm	—	—	-93.9	dB	7	Zone II'

Note) 1. Converted value into mV using 1Digit = 0.2445 mV for 12-bit output.
2. The video signal shading is the measured value in the wafer status and does not include characteristics of the seal glass.

Zone Definition of Video Signal Shading

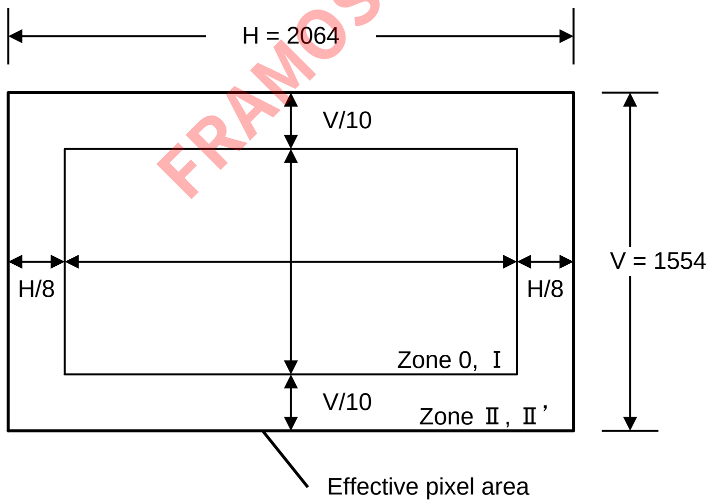


Image Sensor Characteristics Measurement Method

Measurement Conditions

In the following measurements, the device drive conditions are at the typical values of the bias conditions and clock voltage conditions.
In the following measurements, spot pixels are excluded and, unless otherwise specified, the optical black (OB) level is used as the reference for the signal output, which is taken as the value of the signal output of the measurement system.

Color Coding of Physical Pixel Array

The primary color filters of this image sensor are arranged in the layout shown in the figure below. Gr and Gb represent the G signal on the same line as the R and B signals, respectively. The Gb signal and B signal lines and the R signal and Gr signal lines are output successively.

Gb	B	Gb	B
R	Gr	R	Gr
Gb	B	Gb	B
R	Gr	R	Gr

Color Coding Diagram

Definition of standard imaging conditions

◆ Standard imaging condition I:
Use a pattern box (luminance: 706 cd/m^2, color temperature of 3200 K halogen source) as a subject. (Pattern for evaluation is not applicable.) Use a testing standard lens with CM500S (t = 1.0 mm) as an IR cut filter and image at F5.6. The luminous intensity to the sensor receiving surface at this point is defined as the standard sensitivity testing luminous intensity.

◆ Standard image condition II:
Image a light source (color temperature of 3200 K) with a uniformity of brightness within 2 % at all angles. Use a testing standard lens with CM500S (t = 1.0 mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.

◆ Standard image condition III:
Image a light source (color temperature of 3200 K) with a uniformity of brightness within 2 % at all angles. Use a testing standard lens (exit pupil distance -100 mm) with CM500S (t = 1.0 mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.

Measurement Method

1. Sensitivity
   Set the measurement condition to the standard imaging condition I. After setting the electronic shutter mode with a shutter speed of 1/100 s, measure the Gr and Gb signal outputs (VGr, VGb) at the center of the screen, and substitute the values into the following formula.

   $$S = (VGr + VGb) \times 100/30\ [mV]$$

2. Sensitivity ratio
   Set the measurement condition to the standard imaging condition II. After adjusting the average value of the Gr and Gb signal outputs to 573 mV, measure the R signal output (VR [mV]), the Gr and Gb signal outputs (VGr, VGb [mV]) and the B signal output (VB [mV]) at the center of the screen in frame readout mode, and substitute the values into the following formulas.

   $$VG = (VGr + VGb) / 2$$
   $$RG = VR / VG$$
   $$BG = VB / VG$$

3. Saturation signal
   Set the measurement condition to the standard imaging condition II. After adjusting the luminous intensity to 10 times the intensity with the average value of the Gr and Gb signal outputs, 573 mV, measure the minimum values of the Gr, Gb, R and B signal outputs.

4. Video signal shading
   Set the measurement condition to the standard imaging condition III. With the lens diaphragm at F2.8, adjust the luminous intensity so that the average value of the Gr and Gb signal outputs are 573 mV. Then measure the maximum value (Gmax [mV]) and the minimum value (Gmin [mV]) of the Gr and Gb signal outputs, and substitute the values into the following formula.

   $$SH = (Gmax - Gmin) / 573 \times 100\ [\%]$$

5. Dark signal
   With the device junction temperature of 60 ˚C and the device in the light-obstructed state, divide the output difference between 1/3 s integration at 3 frame/s and 1/30 s integration at 30 frame/s by 9, and calculate the signal output converted to 1/30 s integration. Measure the average value of this output (Vdt [mV]).

6. Dark signal shading
   Measure the maximum value (Vdmax [mV]) and the minimum value (Vdmin [mV]) of the dark signal output with the device junction temperature of 60 ˚C and the device in the light-obstructed state and 1/30 s integration. The measuring values substitute into the following formula.

   $$\Delta Vdt = Vdmax - Vdmin\ [mV]$$

7. PLS
   Set the measurement condition to the standard imaging condition II, the Gr and Gb output signal Vave measured by standard image condition. Then, adjust the luminous intensity to 500 times the intensity with average value of the Gr and Gb signal output, Vave. When the charge drain is executed be the electronic shutter and the condition that not be readout from photo diode to analog memory, readout by dropping to 1/113 frame rate.

   $$Sm = 20 \times \log((Vsm/Vave) \times (1/500) \times (1/113))\ [dB]$$

Setting Registers Using Serial Communication

Description of Setting Registers (4-wire)

The serial data input order is LSB-first transfer. The table below shows the various data types and descriptions.

Serial Data Transfer Order

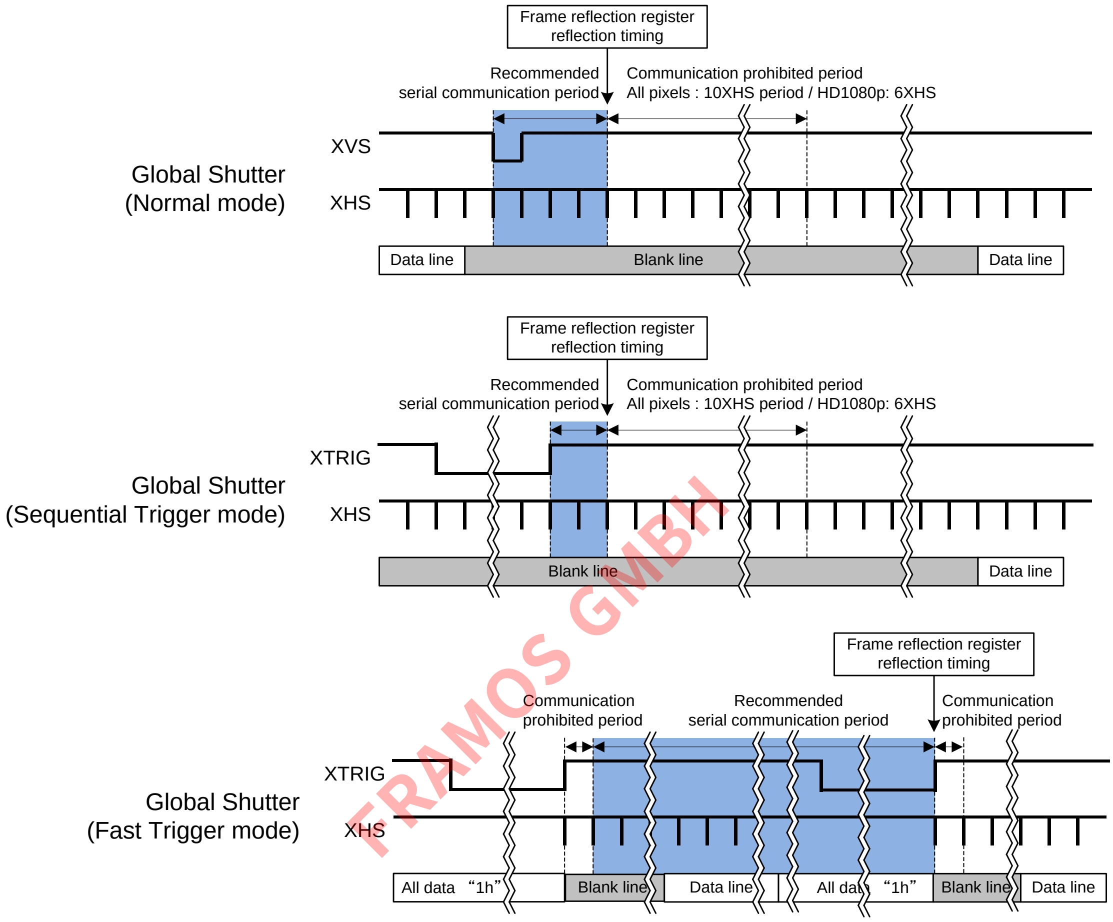
Chip ID	Start address	Data	Data	Data	…
(8 bit)	(8 bit)	(8 bit)	(8 bit)	(8 bit)	(8 bit)

Type and Description

Type	Description
Chip ID	Chip ID: 02 Write: 02h / Read: 82h
	Chip ID: 03 Write: 03h / Read: 83h
	Chip ID: 04 Write: 04h / Read: 84h
	Chip ID: 05 Write: 05h / Read: 85h
	Chip ID: 06 Write: 06h / Read: 86h
	Chip ID: 07 Write: 07h / Read: 87h
	Chip ID: 08 Write: 08h / Read: 88h
	Chip ID: 09 Write: 09h / Read: 89h
	Chip ID: 0A Write: 0Ah / Read: 8Ah
	Chip ID: 0B Write: 0Bh / Read: 8Bh
	Chip ID: 0C Write: 0Ch / Read: 8Ch
	Chip ID: 0D Write: 0Dh / Read: 8Dh
	Chip ID: 0E Write: 0Eh / Read: 8Eh
	Chip ID: 0F Write: 0Fh / Read: 8Fh
	Chip ID: 10 Write: 10h / Read: 90h
	Chip ID: 11 Write: 11h / Read: 91h
	Chip ID: 12 Write: 12h / Read: 92h
Address	Designate the address according to the Register Map. When using a communication method that designates continuous addresses, the address is automatically incremented from the previously transmitted address.
Data	Input the setting values according to the Register Map.

Register Communication Timing (4-wire)

Perform serial communication in sensor standby mode or within communication period. For the registers marked "V" in the item of Reflection timing, when the communication is performed in the communication period shown in the figure below they are reflected by frame reflection timing. For the registers noted “Immediately” in the item of Reflection timing, the settings are reflected when the communication is performed. (For the immediate reflection registers, set them in sensor standby state.)



Register Write and Read (4-wire)

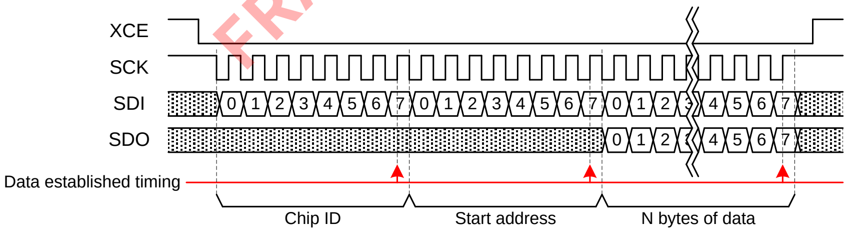
◆ Follow the communication procedure below when writing registers.

(1) Set XCE Low to enable the chip's communication function. Serial data input is executed using SCK and SDI.
(2) Transmit data in sync with SCK 1 bit at a time from the LSB using SDI. Transfer SDI in sync with the falling edge of SCK. (The data is loaded at the rising edge of SCK.)
(3) Input the Chip ID (CID = 02h to 12h) to the first byte. If the Chip ID differs, subsequent data is ignored.
(4) Input the start address to the second byte. The address is automatically incremented.
(5) Input the data to the third and subsequent bytes. The data in the third byte is written to the register address designated by the second byte, and the register address is automatically incremented thereafter when writing the data for the fourth and subsequent bytes. Normal register data is loaded to the inside of the sensor and established in 8-bit units.
(6) The register values starting from the register address designated by the second byte are output from the SDO pin. The register values before the write operation are output. The actual register values are the input data.
(7) Set XCE High to end communication.

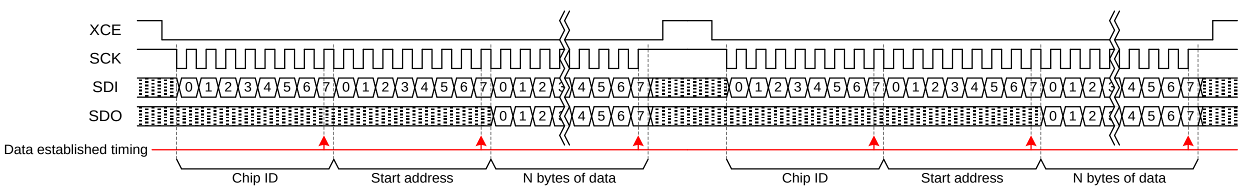
◆ Follow the communication procedure below when reading registers.

(1) Set XCE Low to enable the chip's communication function. Serial data input is executed using SCK and SDI.
(2) Transmit data in sync with SCK 1 bit at a time from the LSB using SDI. Transfer SDI in sync with the falling edge of SCK. (The data is loaded at the rising edge of SCK.)
(3) Input Chip ID (CID = 82h to 92h) to the first byte. If the Chip ID differs, subsequent data is ignored.
(4) Input the start address to the second byte. The address is automatically incremented.
(5) Input data to the third and subsequent bytes. Input dummy data in order to read the registers. The dummy data is not written to the registers. To read continuous data, input the necessary number of bytes of dummy data.
(6) The register values starting from the register address designated by the second byte are output from the SDO pin. The input data is not written, so the actual register values are output.
(7) Set XCE High to end communication.

Note) When writing data to multiple registers with discontinuous addresses, access to undesired registers can be avoided by repeating the above procedure multiple times.



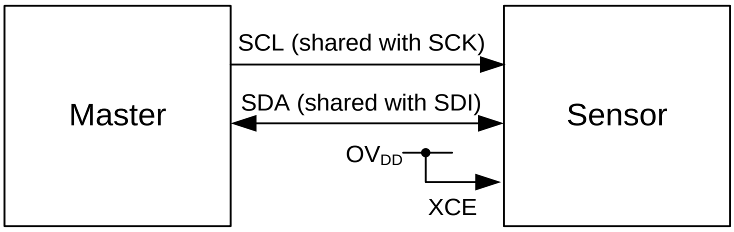
Serial Communication (Continuous Addresses)



Serial Communication (Discontinuous Addresses)

Description of Setting Registers (I^2C)

The serial data input order is MSB-first transfer. The table below shows the various data types and descriptions.



Pin connection of serial communication

This sensor can be set two slave addresses with the common I^2C bus by switching the polarity of SLAMODE Pin.

SLAVE Address (SLAMODE = 0)

MSB							LSB
0	0	1	0	0	0	0	R / W

SLAVE Address (SLAMODE = 1)

MSB							LSB
0	0	1	1	0	1	0	R / W

* R/W is data direction bit

R/W

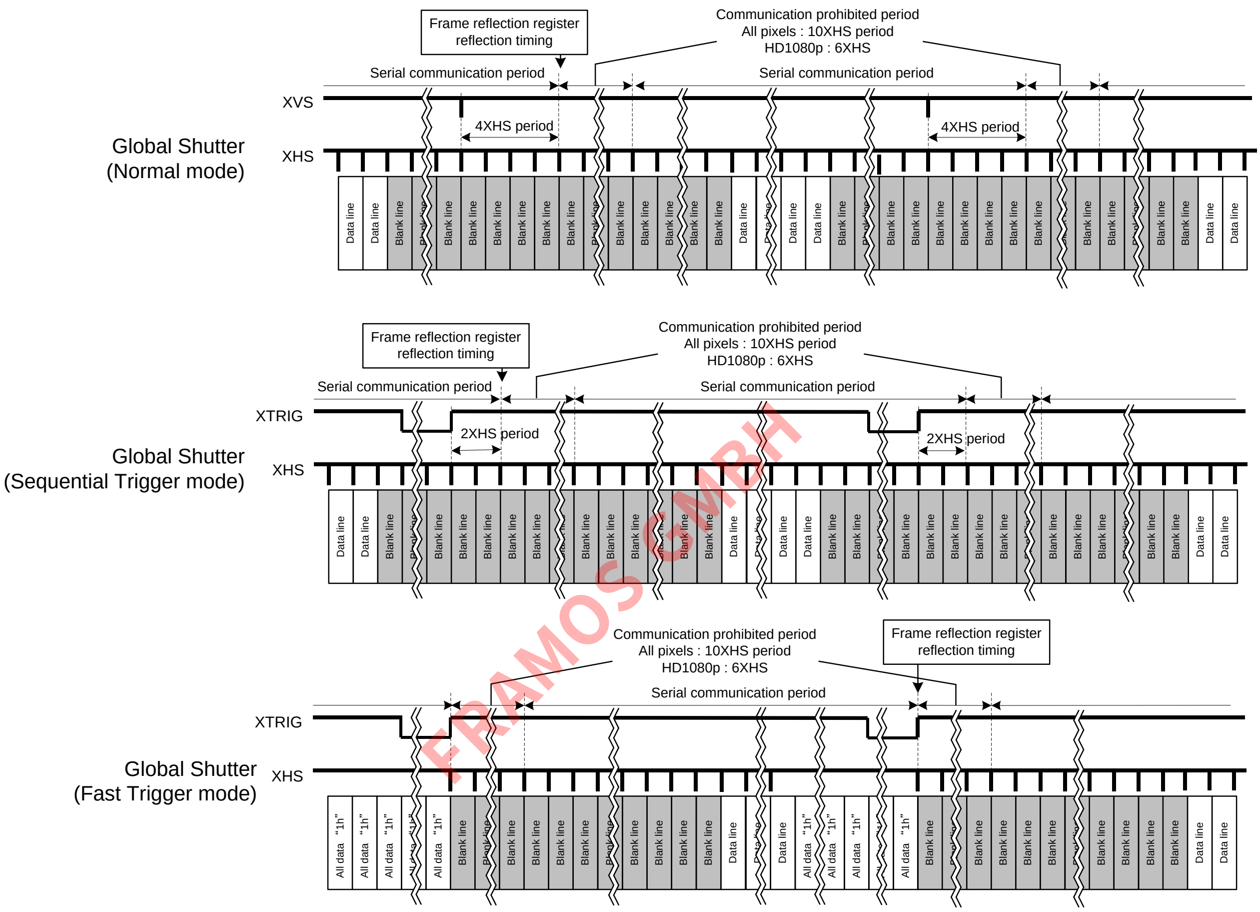
R / W bit	Data direction
0	Write (Master → Sensor)
1	Read (Sensor → Master)

I^2C pin description

Symbol	Pin No.	Description
SCL (common to SCK)	L3	Serial clock input
SDA (common to SDI)	M3	Serial data communication

Register Communication Timing (I²C)

In I²C communication system, communication can be performed excluding during the period when communication is prohibited from the falling edge of XVS to 4H after.
For the registers marked "V" in the item of Reflection timing, when the communication is performed in the communication period shown in the figure below they are reflected by frame reflection timing. For the registers noted “Immediately” in the item of Reflection timing, the settings are reflected when the communication is performed. (For the immediate reflection registers other than STANDBY, REGHOLD, XMSTA set them in sensor standby state.)
Using REG_HOLD function is recommended for register setting using I²C communication. For REG_HOLD function, see “Register Transmission Setting” in “Description of Functions”.



I²C Communication Protocol

I²C serial communication supports a 16-bit register address and 8-bit data message type.

S	Slave Address [7:1]	R / W	A	Register Address [15:8]	A	Register Address [7:0]	A	DATA [7:0]	A / $\overline{A}$	P

From Master to Slave

From Slave to Master

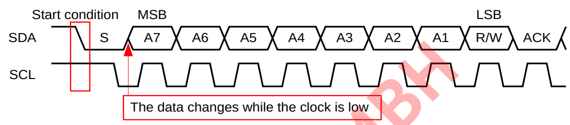
Direction depend on operation

S : Start Condition
Sr : Repeated Start Condition
P : Stop Condition
A : Acknowledge
$\overline{A}$: Negative Acknowledge

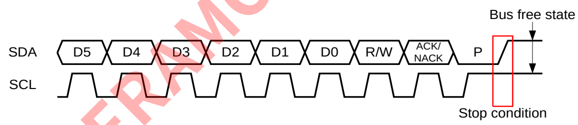
R/W=
0: Write (Master → Sensor)
1: Read (Sensor → Master)

Communication protocol

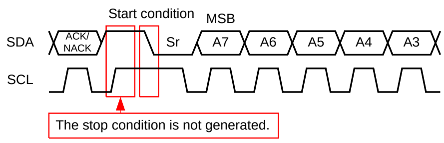
Data is transferred serially, MSB first in 8-bit units. After each data byte is transferred, A (Acknowledge) / $\overline{A}$ (Negative Acknowledge) is transferred. Data (SDA) is transferred at the clock (SDL) cycle. SDA can change only while SCL is Low, so the SDA value must be held while SCL is High. The Start Condition is defined by SDA changing from High to Low while SCL is High. When the Stop Condition is not generated in the previous communication phase and Start Condition for the next communication is generated, that Start Condition is recognized as a Repeated Start Condition.



Start Condition

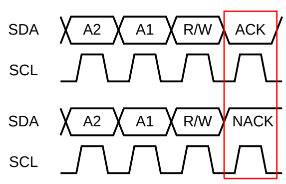


Stop Condition



Repeated Start Condition

After transfer of each data byte, the Master or the sensor transmits an Acknowledge / Negative Acknowledge and release (does not drive) SDA. When Negative Acknowledge is generated, the Master must immediately generate the Stop Condition and end the communication.



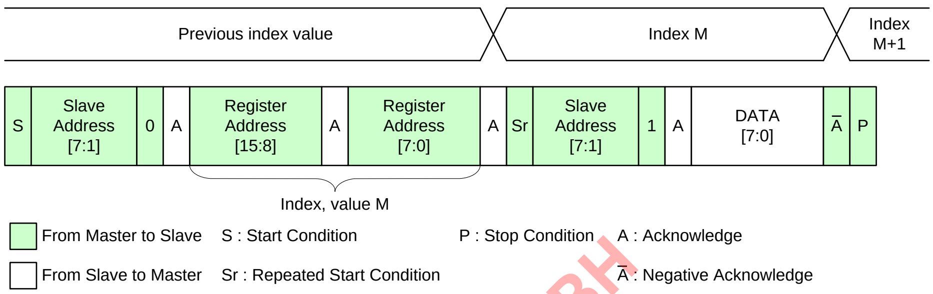
Acknowledge and Negative Acknowledge

I²C Serial Communication Read/Write Operation

This sensor supports the following four read operations and two write operations.

Single Read from Random Location

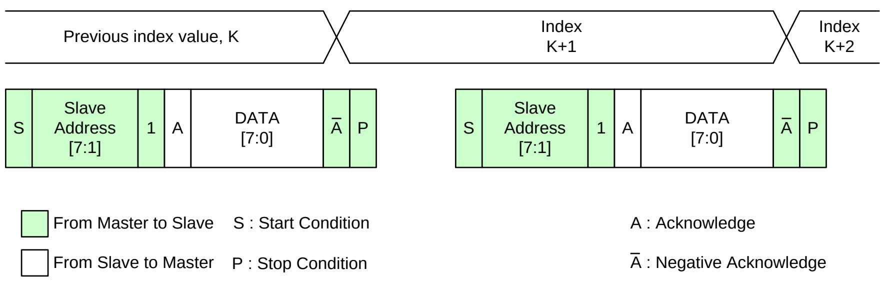
The sensor has an index function that indicates which address it is focusing on. In reading the data at an optional single address, the Master must set the index value to the address to be read. For this purpose it performs dummy write operation up to the register address. The upper level of the figure below shows the sensor internal index value, and the lower level of the figure shows the SDA I/O data flow. The Master sets the sensor index value to M by designating the sensor slave address with a write request, then designating the address (M). Then, the Master generates the Start Condition. The Start Condition is generated without generating the Stop Condition, so it becomes the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge immediately followed by the index address data on SDA. After the Master receives the data, it generates a Negative Acknowledge and the Stop Condition to end the communication.



Single Read from Random Location

Single Read from Current Location

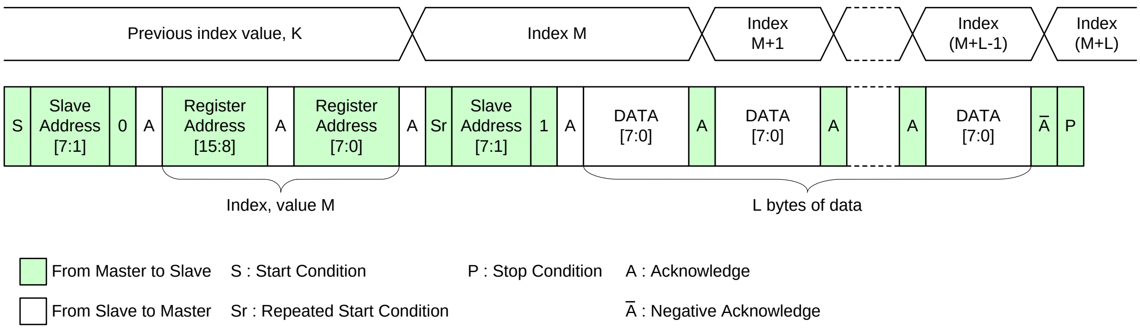
After the slave address is transmitted by a write request, that address is designated by the next communication and the index holds that value. In addition, when data read/write is performed, the index is incremented by the subsequent Acknowledge/Negative Acknowledge timing. When the index value is known to indicate the address to be read, sending the slave address with a read request allows the data to be read immediately after Acknowledge. After receiving the data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication, but the index value is incremented, so the data at the next address can be read by sending the slave address with a read request.



Single Read from Current Location

Sequential Read Starting from Random Location

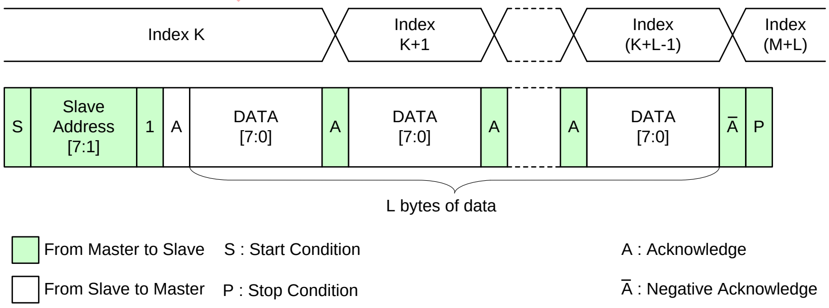
In reading data sequentially, which is starting from an optional address, the Master must set the index value to the start of the addresses to be read. For this purpose, dummy write operation includes the register address setting. The Master sets the sensor index value to M by designating the sensor slave address with a read request, then designating the address (M). Then, the Master generates the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge followed immediately by the index address data on SDA. When the Master outputs an Acknowledge after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA. This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.



Sequential Read Starting from Random Location

Sequential Read Starting from Current Location

When the index value is known to indicate the address to be read, sending the slave address with a read request allows the data to be read immediately after the Acknowledge. When the Master outputs an Acknowledge after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA. This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.



Sequential Read Starting from Current Location

Register Map

This sensor has a total of 4352 bytes of registers, composed of registers with address 00h to FFh that correspond to Chip ID = 02h to 12h. Use the initial values for empty address. Some registers must be change from the initial values, so the sensor control side should be capable of setting 4352 bytes.

There are two different register reflection timing. Values are reflected immediately after writing to register noted as “Immediately”, or at the frame reflection register reflection timing described in the item of “Register Communication Timing” in the section of “Setting Registers with Serial Communication” for registers noted as “V” in the Reflection timing column of the Register Map. For the immediate reflection registers below, set them in sensor standby state.

・INCKSEL0
・INCKSEL1
・INCKSEL2
・INCKSEL3

For the register that is writing "*" to the setting value in description, change the value from the default value after the reset.

Do not perform communication to addresses not listed in the Register Map. Doing so may result in operation errors.

Chip ID = 02 (Write: Chip ID = 02h, Read: Chip ID = 82h, I^2C: 30**h)

Please refer to the other register map file for the register that has not been described.

Address 4-wire	Address I^2C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
00h	3000h	0	STANDBY [0]	Standby mode 0: Normal operation 1: Standby	1	01h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
08h	3008h	0	REGHOLD [0]	Register hold (Function not to update V reflection registers) 0: Invalid 1: Valid	0	00h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0A	300Ah	0	XMSTA [0]	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop	1	01h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0Bh	300Bh	0	TRIGEN [0]	Global shutter mode setting 0: Normal mode 1: Trigger mode	0	00h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
0Dh	300Dh	0	WINMODE [3:0]	Drive mode setting of V direction 0h: All-pixel 1h: 1/2 Subsampling mode Ch: Full-HD Others: Setting prohibited	0	00h	Immediately
		1			0		
		2			0		
		3			0		
		4	HMODE[0]	Drive mode setting of H direction 0: All-pixel 1: 1/2 Subsampling mode	0		V
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0Eh	300Eh	0	VREVERSE [0]	Vertical (V) direction readout inversion control 0: Normal 1: Inverted	0	00h	Immediately
		1	HREVERSE [0]	Horizontal (H) direction readout inversion control 0: Normal 1: Inverted	0		V
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
10h	3010h	0	VMAX [19:0]	LSB When sensor master mode vertical span setting. (Number of operation lines count from 1) MSB	0082Eh	2Eh	V
		1					
		2					
		3					
		4					
		5					
		6					
		7					
11h	3011h	0				08h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
12h	3012h	0				00h	
		1					
		2					
		3					
		4		Fixed to 0	0		
		5		Fixed to 0	0		
		6		Fixed to 0	0		
		7		Fixed to 0	0		

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
14h	3014h	0	HMAX [15:0]	LSB	015Eh	5Eh	V
		1					
		2					
		3					
		4					
		5					
		6		When sensor master mode horizontal span setting. (Number of operation clocks count from 1)			
		7					
15h	3015h	0				01h	
		1					
		2					
		3					
		4					
		5					
		6					
		7		MSB			
19h	3019h	0	CKSEL [0]	The value is set according to drive mode. 0: All-pixel, ROI, 1/2 Subsampling 1: 1080p-Full HD	0	00h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
26h	3026h	0	TOUT1SEL[1:0]	TOUT1 pin setting 0h: Low fixed 3h: Pulse output	0h	00h	Immediately
		1					
		2	TOUT2SEL [1:0]	TOUT2 pin setting 0h: Low fixed 3h: Pulse output	0h		Immediately
		3					
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
29h	3029h	0, 1, 2	TRIG_TOUT1_SEL [2:0]	TOUT1 pin setting 0h: Low fixed 1h: Pulse1 output	0h	00h	Immediately
		3		Fixed to 0	0		—
		4, 5, 6	TRIG_TOUT2_SEL [2:0]	TOUT2 pin setting 0h: Low fixed 2h: Pulse2 output	0h		Immediately
		7		Fixed to 0	0		—
36h	3036h	0		Fixed to 0	0	C0h	—
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4, 5	SYNCSEL	XHS, XVS pin setting 0h: Normal Output 3h: Hi-Z	0h		Immediately
		6		Fixed to 1	1		—
		7		Fixed to 1	1		—
6Dh	306Dh	0	PULSE1_EN_NOR [0]	Pulse1 output in normal mode 0: Disable 1: Enable	0	00h	Immediately
		1	PULSE1_EN_TRIG [0]	Pulse1 output in trigger mode 0: Disable 1: Enable	0		Immediately
		2	PULSE1_POL	Pulse1 polarity selection 0: High active 1: Low active	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
70h	3070h	0, 1, 2, 3, 4, 5, 6, 7	PULSE1_UP [19:0]	LSB Pulse1 active period start timing setting Designated in line units from reference point (For details, see the "Pulse Output Function") MSB	00000h	00h	Immediately
71h	3071h	0, 1, 2, 3, 4, 5, 6, 7				00h	
72h	3072h	0, 1, 2, 3				00h	
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
74h	3074h	0	PULSE1_DN [19:0]	LSB	00000h	00h	Immediately
		1					
		2					
		3					
		4					
		5					
		6					
		7					
75h	3075h	0		Pulse1 active period end timing setting Designated in line units from readout start (For details, see the "Pulse Output Function")		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
76h	3076h	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
79h	3079h	0	PULSE2_EN_NOR [0]	Pulse2 output in normal mode 0: Disable 1: Enable	0	00h	Immediately
		1	PULSE2_EN_TRIG [0]	Pulse2 output in trigger mode 0: Disable 1: Enable	0		Immediately
		2	PULSE2_POL [0]	Pulse2 polarity selection 0: High active 1: Low active	0		Immediately
		3		Fixed to 1	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
7Ch	307Ch	0	PULSE2_UP [19:0]	LSB	00000h	00h	Immediately
		1					
		2					
		3					
		4					
		5					
		6					
		7					
7Dh	307Dh	0		Pulse2 active period start timing setting Designated in line units from reference point (For details, see the "Pulse Output Function")		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
7Eh	307Eh	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
80h	3080h	0	PULSE2_DN [19:0]	LSB	00000h	00h	Immediately
		1					
		2					
		3					
		4					
		5					
		6					
		7					
81h	3081h	0		Pulse2 active period end timing setting Designated in line units from reference point (For details, see the "Pulse Output Function")		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
82h	3082h	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
89h	3089h	[7:0]	INCKSEL0 [7:0]	Set according to INCK frequency and drive mode.	20h	20h	Immediately
8Ah	308Ah	[7:0]	INCKSEL1 [7:0]	Set according to INCK frequency and drive mode.	00h	00h	Immediately
8Bh	308Bh	[7:0]	INCKSEL2 [7:0]	Set according to INCK frequency and drive mode.	20h	20h	Immediately
8Ch	308Ch	[7:0]	INCKSEL3 [7:0]	Set according to INCK frequency and drive mode.	00h	00h	Immediately
8Dh	308Dh	0	SHS [19:0]	LSB	0000Ah	0Ah	V
		1					
		2					
		3					
		4					
		5					
		6					
		7					
8Eh	308Eh	0		Storage time adjustment Designated in line unit		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
8Fh	308Fh	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
9Eh	309Eh	[7:0]	GTWAIT [7:0]	The value is set according to drive mode. 08h: All-pixel, ROI, 1/2 Subsampling: 06h: 1080p-Full HD: 06h	0Ah	0Ah	Immediately

Address		bit	Register Name	Description	Default value after reset		Reflection timing
4-wire	I^2C				By register	By address	
A0h	30A0h	[7:0]	GSDLY [7:0]	The value is set according to drive mode. 04h: All-pixel, ROI, 1/2 Subsampling 02h: 1080p-Full HD	08h	08h	Immediately
AAh	30AAh	0	VINT_EN	Setting of Interrupt mode in Trigger Mode 0: V interrupt is disable 1: V interrupt is enable	1	01h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
AEh	30AEh	0	LOWLAGTRG	Selection of trigger mode 0: Sequential trigger mode 1: Fast trigger mode	0	00h	Immediately
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
AFh	30AFh	[7:0]		The value is set according to drive mode. 0Eh: All-pixel, ROI, 1/2 Subsampling 0Ah: 1080p-Full HD	06h	06h	—

Chip ID = 03 (Write: Chip ID = 03h, Read: Chip ID = 83h, I^2C: 31h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 04 (Write: Chip ID = 04h, Read: Chip ID = 84h, I²C: 32**h)

Please refer to the other register map file for the register that has not been described.

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
04h	3204h	0	GAIN [8:0]	LSB	000h	00h	V
		1					
		2		Gain setting			
		3		0 dB (000d) to 48 dB (480d)			
		4		0.1 dB Step			
		5		(Refer to Address 12h about detail of			
		6		Reflection Timing.)			
		7					
05h	3205h	0		MSB		00h	
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
12h	3212h	[7:0]	GAINDLY	Setting of Gain Reflection Timing at Normal mode. 08h: Gain reflect at the frame 09h: Gain reflect at the next frame (Same timing as SHS reflecting output.) Others: Setting prohibited	00h	00h	V
54h	3254h	0	BLKLEVEL [11:0]	LSB	03Ch	3Ch	V
		1					
		2					
		3					
		4					
		5		Black level offset value setting			
		6		Recommended value:			
		7		0F0h: 12 bit			
55h	3255h	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

Chip ID = 05 (Write: Chip ID = 05h, Read: Chip ID = 85h, I^2C: 33**h)

Please refer to the other register map file for the register that has not been described.

Address		bit	Register Name	Description	Default value after reset		Reflection timing
4-wire	I^2C				By register	By address	
00h	3300h	0	FID0_ROIH1ON [0]	The horizontal setting of FID0 ROI area (1, 1) 0: Disable 1: Enable	0	00h	V
		1	FID0_ROIV1ON [0]	The vertical setting of FID0 ROI area (1, 1) 0: Disable 1: Enable	0		Immediately
		[7:2]		Fixed to 0	00h		—
10h	3310h	[7:0]	FID0_ROIPH1 [12:0]	Designation of horizontal cropping position for FID0 on area (1, 1) *Set the value of multiple of 4	0000h	00h	V
11h	3311h	[4:0]				00h	
		[7:5]		Fixed to 0h	0h		—
12h	3312h	[7:0]	FID0_ROIPV1 [11:0]	Designation of vertical cropping position for FID0 on area (1, 1) *Set the value of multiple of 4	000h	00h	Immediately
13h	3313h	[3:0]				00h	
		[7:4]		Fixed to 0h	0h		—
14h	3314h	[7:0]	FID0_ROIWH1 [12:0]	Designation of horizontal cropping size for FID0 on area (1, 1) *Set the value of multiple of 4	0000h	00h	V
15h	3315h	[4:0]				00h	
		[7:5]		Fixed to 0h	0h		—
16h	3316h	[7:0]	FID0_ROIWV1 [11:0]	Designation of vertical cropping size for FID0 on area (1, 1) *Set the value of multiple of 4	000h	00h	Immediately
17h	3317h	[3:0]				00h	
		[7:4]		Fixed to 0h	0h		—

Chip ID = 06 (Write: Chip ID = 06h, Read: Chip ID = 86h, I^2C: 34**h)

Please refer to the other register map file for the register that has not been described.

Chip ID = 07 (Write: Chip ID = 07h, Read: Chip ID = 87h, I^2C: 35**h)

Please refer to the other register map file for the register that has not been described.

Chip ID = 08 (Write: Chip ID = 08h, Read: Chip ID = 88h, I^2C: 36**h)

Please refer to the other register map file for the register that has not been described.

Chip ID = 09 (Write: Chip ID = 09h, Read: Chip ID = 89h, I^2C: 37**h)

Please refer to the other register map file for the register that has not been described.

Chip ID = 0A (Write: Chip ID = 0Ah, Read: Chip ID = 8Ah, I^2C: 38**h)

Please refer to the other register map file for the register that has not been described.

Chip ID = 0B (Write: Chip ID = 0Bh, Read: Chip ID = 8Bh, I^2C: 39**h)

Please refer to the other register map file for the register that has not been described.

Chip ID = 0C (Write: Chip ID = 0Ch, Read: Chip ID = 8Ch, I^2C: 3Ah)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0D (Write: Chip ID = 0Dh, Read: Chip ID = 8Dh, I^2C: 3Bh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0E (Write: Chip ID = 0Eh, Read: Chip ID = 8Eh, I^2C: 3Ch)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0F (Write: Chip ID = 0Fh, Read: Chip ID = 8Fh, I^2C: 3Dh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 10 (Write: Chip ID = 10h, Read: Chip ID = 90h, I^2C: 3Eh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 11 (Write: Chip ID = 11h, Read: Chip ID = 91h, I^2C: 3Fh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 12 (Write: Chip ID = 12h, Read: Chip ID = 92h, I^2C: 40h)**

Please refer to the other register map file for the register that has not been described.

Readout Drive Modes

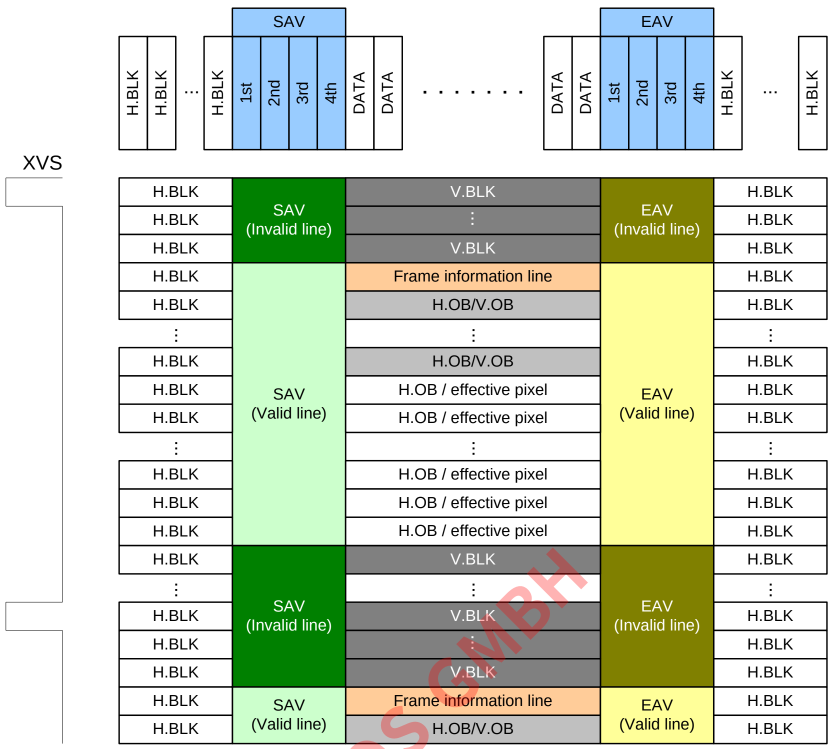
The table below lists the operating modes available with this sensor. (Each value is the Max.frame rate of the each number of ch.)

Drive mode	Frame rate [frame/s]	Data rate [Gbps]	Serial LVDS ch*1	A/D conversion	Number of recording pixels		Total number of pixels*2		Number of INCK in 1H		
					H	V	H	V	INCK: 37.125 MHz	INCK: 74.25 MHz	INCK: 54 MHz
All pixel	55.6	2.376	4	12	2048	1536	2256	1576	423.0	846.0	615.3
All pixel (Vertical / Horizontal 1/2 subsampling)	116.6	2.376	4	12	1024	768	2212	804	396.0	792.0	576.0
HD1080p	60	1.782	4	12	1920	1080	2200	1125	550.0	1100.0	—
	30						4400		1100.0	2200.0	—
ROI	*4	2.376	4	12	*3	*3	2256	*4	423.0	846.0	615.3

*1 The data rate of each output channel is value that is obtained by total data rate divided by the number of channels.
Example) In All-pixel 55.6 [frame/s] mode: 2.736 [Gbps] / 4 = 594 [Mbps]
*2 For the setting value to register HMAX / VMAX, see the section of each drive mode settings
*3 Designated cropping area (ROI)
*4 See the section of “ROI mode”

Sync code

The sync code is added immediately before and after "dummy signal + OB signal + effective pixel data" and then output. The sync code is output in order of 1st, 2nd, 3rd and 4th. The fixed value is output for 1st to 3rd. (BLK: Blanking period)



Sync Code Output Timing

List of Sync Code

Sync code	1st code	2nd code	3rd code	4th code
	12 bit	12 bit	12 bit	12 bit
SAV (Valid line)	FFFh	000h	000h	800h
EAV (Valid line)	FFFh	000h	000h	9D0h
SAV (Invalid line)	FFFh	000h	000h	AB0h
EAV (Invalid line)	FFFh	000h	000h	B60h

Sync Code Output Timing

The sensor output signal passes through the internal circuits and is output with a latency time (system delay) relative to the horizontal sync signal. This system delay value is undefined for each line, so refer to the sync codes output from the sensor and perform synchronization.

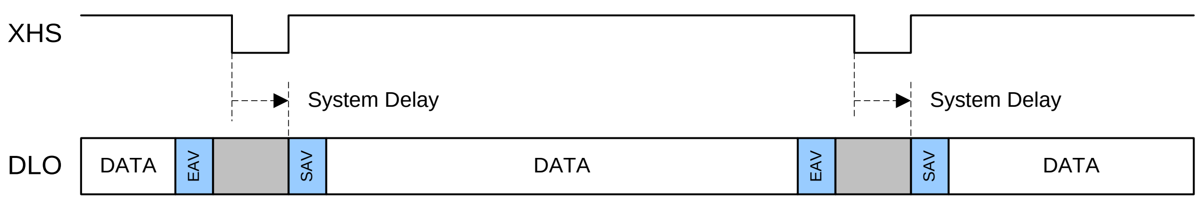


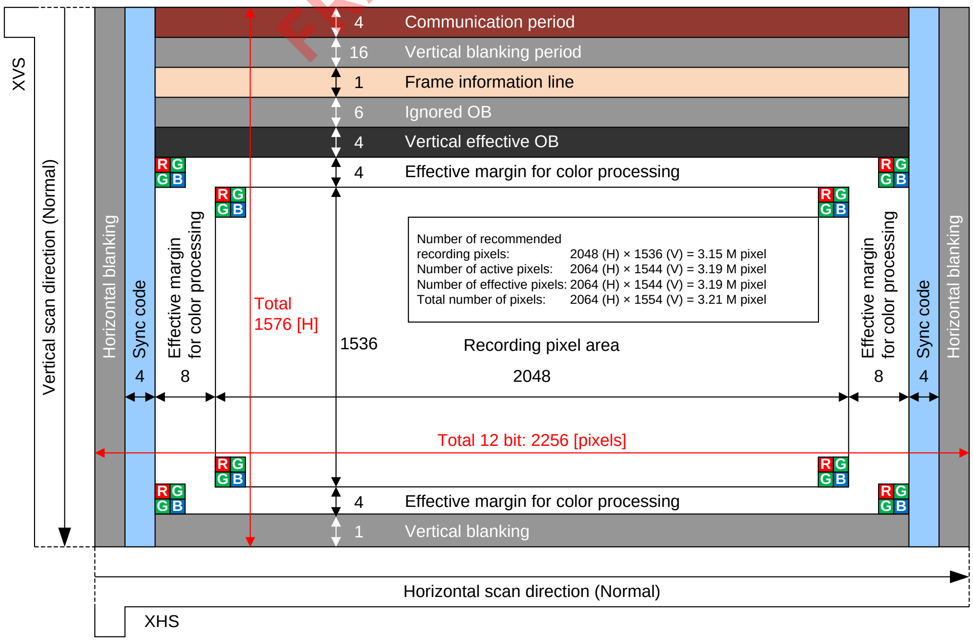
Image Data Output Format

All-pixel scan

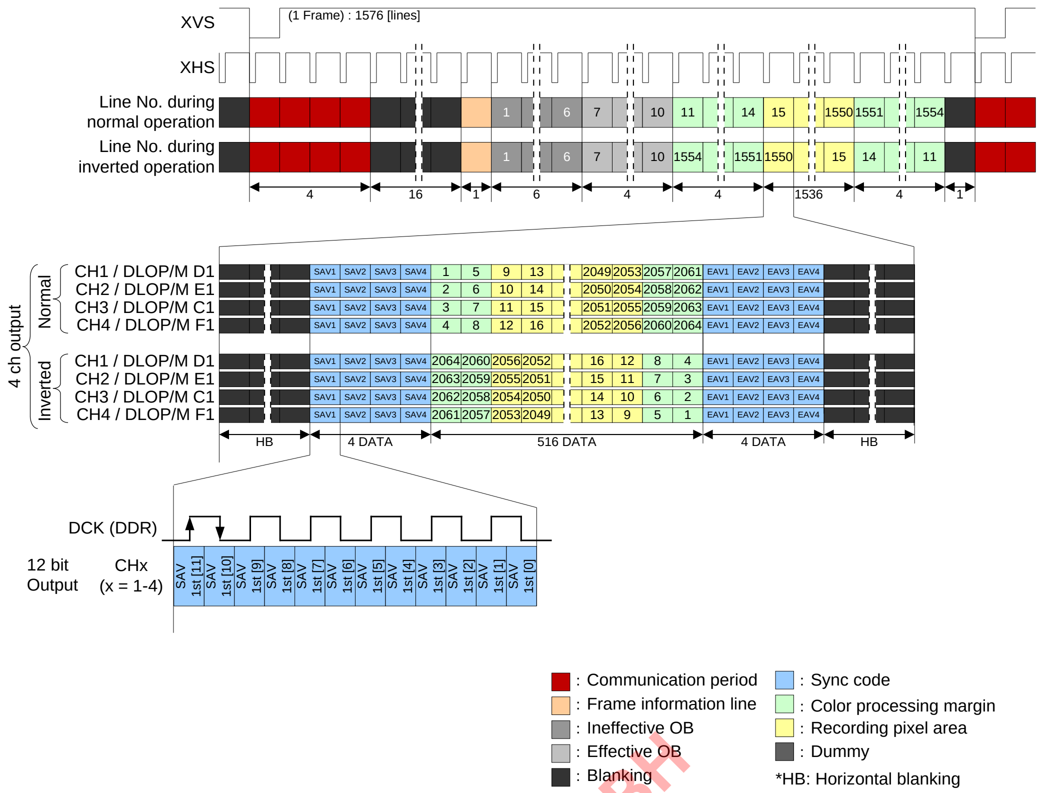
Register List of All-pixel scan mode

Please refer to the other register map file for the register that has not been described.

Address	bit	Register name	Initial Value	Setting value AD = 12 bit 55.6 [frame/s]	Remarks
Chip ID = 02h					
0Dh	[3:0]	WINMODE	0h	0h	All-pixel mode
0Dh	[4]	HMODE	0	0	All-pixel
10h	[7:0]	VMAX	82Eh	628h	1576 line
11h	[7:0]				
12h	[3:0]				
14h	[7:0]	HMAX	15Eh	34Eh	
15h	[7:0]				
19h	[0]	CKSEL	0	0	
89h	[7:0]	INCKSEL0	20h	INCK = 37.125 MHz: 10h INCK = 54 MHz: 16h INCK = 74.25 MHz: 10h	
8Ah	[7:0]	INCKSEL1	00h	INCK = 37.125 MHz: 02h INCK = 54 MHz: 00h INCK = 74.25 MHz: 00h	
8Bh	[7:0]	INCKSEL2	20h	INCK = 37.125 MHz: 10h INCK = 54 MHz: 16h INCK = 74.25 MHz: 10h	
8Ch	[7:0]	INCKSEL3	00h	INCK = 37.125 MHz: 02h INCK = 54 MHz: 00h INCK = 74.25 MHz: 00h	
9Eh	[7:0]	GTWAIT	0Ah	08h	
A0h	[7:0]	GSDLY	08h	04h	
Chip ID = 04h					
54h	[7:0]	BLKLEVEL	03Ch	0F0h	Recommended value
55h	[3:0]				



Pixel Array Image Drawing in All-pixel scan Mode



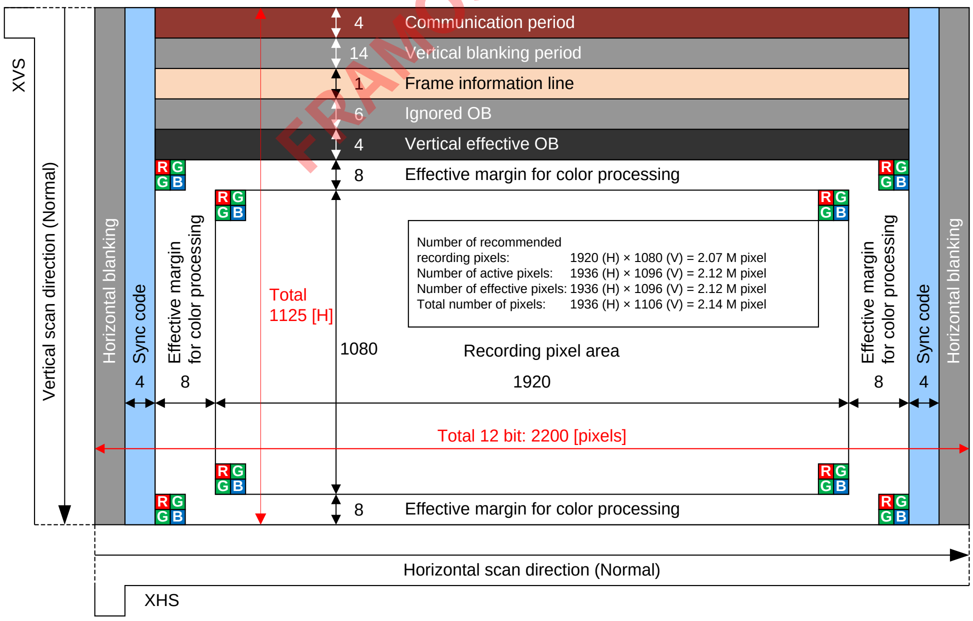
Drive Timing Chart for Serial Output in All-pixel Scan Mode

1080p-Full HD mode

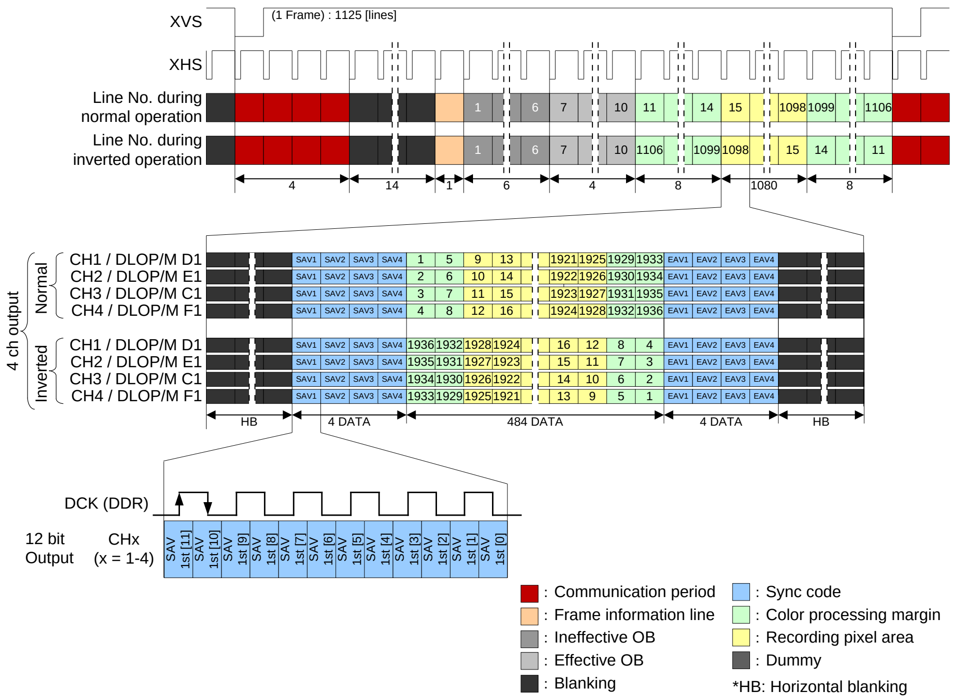
Register List of 1080p-Full HD mode

Please refer to the other register map file for the register that has not been described.

Address	bit	Register name	Initial Value	Setting value AD = 12 bit 60 [frame/s]	Setting value AD = 12 bit 30 [frame/s]	Remarks
Chip ID = 02h						
0Dh	[3:0]	WINMODE	0h	Ch		1080p-FULL HD mode
0Dh	[4]	HMODE	0	0		All-pixel
10h	[7:0]	VMAX	82Eh	465h		1125 line
11h	[7:0]					
12h	[3:0]					
14h	[7:0]	HMAX	15Eh	44Ch	898h	
15h	[7:0]					
19h	[0]	CKSEL	0	1		
89h	[7:0]	INCKSEL0	20h	INCK = 37.125 MHz: 18h INCK = 74.25 MHz: 0Ch		
8Ah	[7:0]	INCKSEL1	00h	INCK = 37.125 MHz: 00h INCK = 74.25 MHz: 00h		
8Bh	[7:0]	INCKSEL2	20h	INCK = 37.125 MHz: 10h INCK = 74.25 MHz: 10h		
8Ch	[7:0]	INCKSEL3	00h	INCK = 37.125 MHz: 02h INCK = 74.25 MHz: 00h		
9Eh	[7:0]	GTWAIT	0Ah	06h		
A0h	[7:0]	GSDLY	08h	02h		
Chip ID = 04h						
54h	[7:0]	BLKLEVEL	03Ch	0F0h		Recommended value
55h	[3:0]					



Pixel Array Image Drawing in 1080p-Full HD Mode



Drive Timing Chart for Serial Output in 1080p-Full HD Mode

ROI mode

This Sensor has ROI function that signals are cut out and read out in a arbitrary position.
Cropping position can set maximum 1 area that specified by horizontal 1 point and vertical 1 point, regarding effective pixel start position as origin (0, 0) in all pixel scan mode. Cropping is available from All-pixel scan mode and horizontal period are fixed to the value for this mode.
This cropped area by horizontal cropping setting (ROI (1, 1)) is output with left justified and that extends the horizontal blanking period. In vertical cropping area (ROI (1, 1)), the number of image data is also output from cropping start line and the frame rate can be adjusted by changing the number of input XVS lines in slave mode or changing register VMAX in master mode.
One invalid frame is generated when the ROI area changing size or cropping address.
ROI image is shown in the figure below.
In case of Vertical / Horizontal 1/2 subsampling mode, this sensor doesn't support ROI mode.

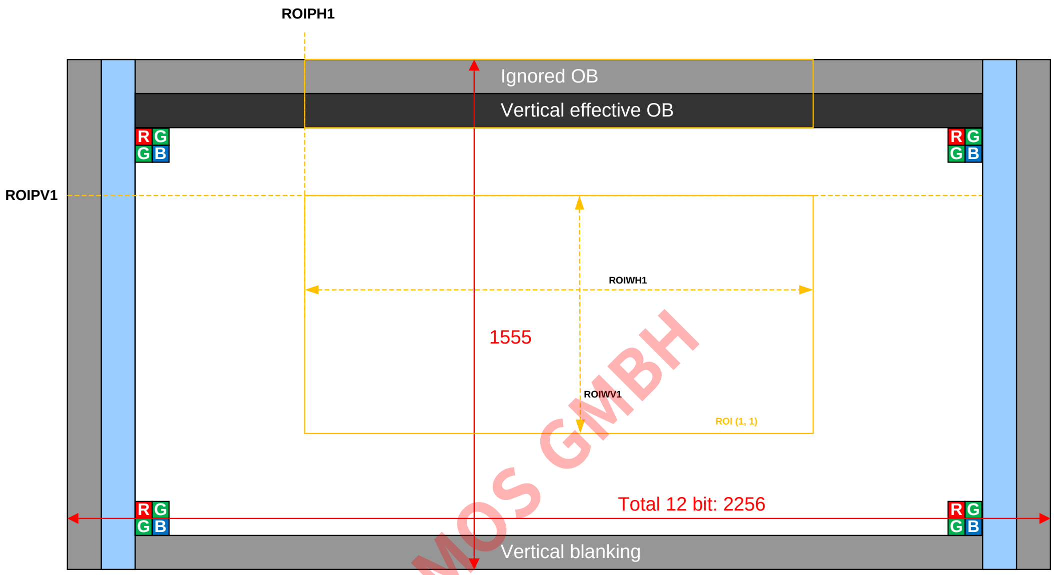
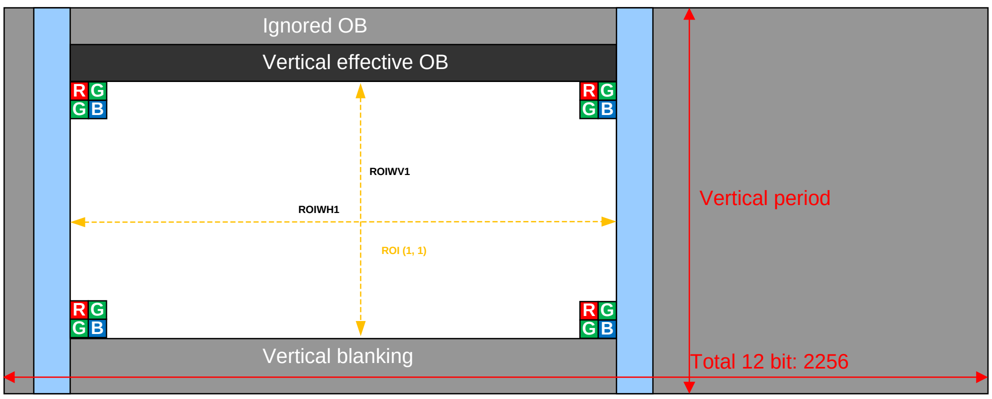


Image Drawing of Designated Areas in ROI Mode



Details of Image Drawing

Register List of ROI mode

Please set All-pixel scan mode to the settings other than the following.

Address	bit	Register name	Initial Value	Setting value AD = 12 bit *1 [frame/s]	Remarks
Chip ID = 02h					
0Dh	[3:0]	WINMODE	0h	0h	All-pixel mode
0Dh	[4]	HMODE	0	0	All-pixel
10h	[7:0]	VMAX	82Eh	*1	
11h	[7:0]				
12h	[3:0]				
14h	[7:0]	HMAX	15Eh	34Eh	
15h	[7:0]				
19h	[0]	CKSEL	0	0	
89h	[7:0]	INCKSEL0	20h	INCK = 37.125 MHz:10h INCK = 54 MHz:16h INCK = 74.25 MHz:10h	
8Ah	[7:0]	INCKSEL1	00h	INCK = 37.125 MHz: 02h INCK = 54 MHz: 00h INCK = 74.25 MHz: 00h	
8Bh	[7:0]	INCKSEL2	20h	INCK = 37.125 MHz:10h INCK = 54 MHz:16h INCK = 74.25 MHz:10h	
8Ch	[7:0]	INCKSEL3	00h	INCK = 37.125 MHz: 02h INCK = 54 MHz: 00h INCK = 74.25 MHz: 00h	
9Eh	[7:0]	GTWAIT	0Ah	08h	
A0h	[7:0]	GSDLY	08h	04h	
Chip ID = 04h					
54h	[7:0]	BLKLEVEL	03Ch	0F0h	Recommended value
55h	[3:0]				
Chip ID = 05h					
00h	[0]	FID0_ROIH1ON	0	The horizontal setting of FID0 ROI area (1, 1) 0: Disable 1: Enable	
	[1]	FID0_ROIV1ON	0	The vertical setting of FID0 ROI area (1, 1) 0: Disable 1: Enable	
10h	[7:0]	FID0_ROIPH1	0000h	Designation of horizontal cropping position for FID0 on area (1, 1) *Set the value of multiple of 4	
11h	[4:0]				
12h	[7:0]	FID0_ROIPV1	000h	Designation of vertical cropping position for FID0 on area (1, 1) *Set the value of multiple of 4	
13h	[3:0]				
14h	[7:0]	FID0_ROIWH1	0000h	Designation of horizontal cropping size for FID0 on area (1, 1) *Set the value of multiple of 4	
15h	[4:0]				
16h	[7:0]	FID0_ROIWV1	000h	Designation of vertical cropping size for FID0 on area (1, 1) *Set the value of multiple of 4	
17h	[3:0]				

Restrictions on ROI mode

The register settings should satisfy following conditions:

ROIPH1 + ROIWH1 < 2064d

ROIPV1 + ROIWV1 < 1544d

* Set the horizontal and vertical setting in multiple of 4.

* Minimum width of the window is as below.
  ROIWH1 $\geq$ 258d

  ROIWV1 $\geq$ 4d

Frame rate on ROI mode

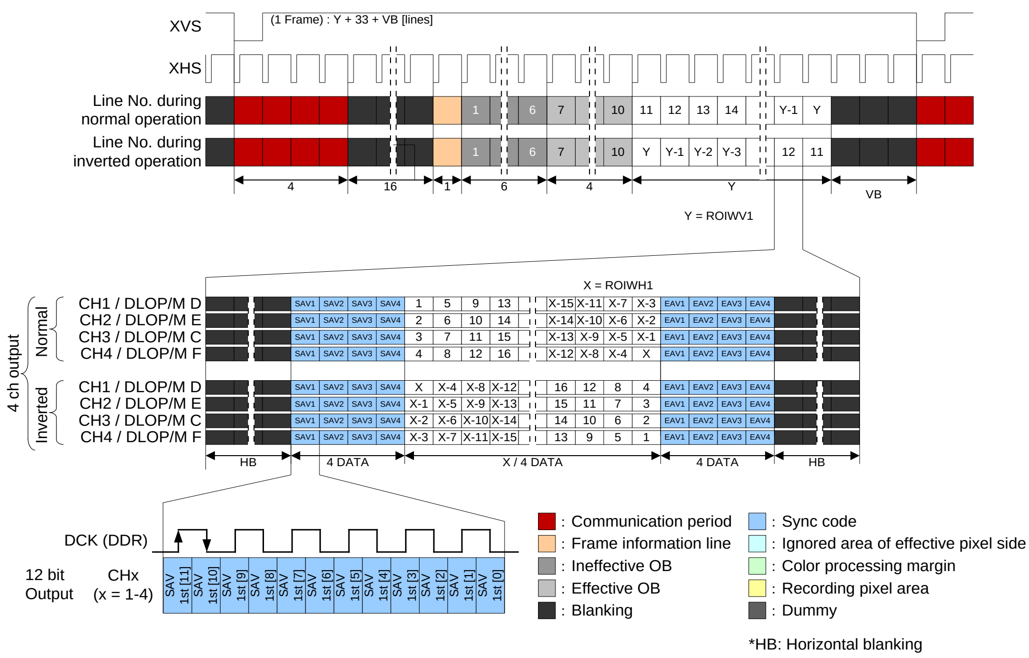
Frame rate [frame/s] = 1 / ((“Number of lines per frame” or VMAX) × (1 H period))

* Number of lines per frame or VMAX = ROIWV1 + 32
* 1 period:
  Calculate by number of INCK in 1 H and the period of INCK.

The example of ROI setting is shown below.
ROIWV1 = 600
ROIWV1 = 4 (minimum value)

Frame rate List of each setting

Register settings No. in register list	1 H period [µs]	Frame rate [frame/s]	
		Total number of ROI: 600 [line]	Total number of ROI: 4 [line]
*1	11.394	138.8	2437.9



Drive Timing Chart for Serial Output in ROI Mode

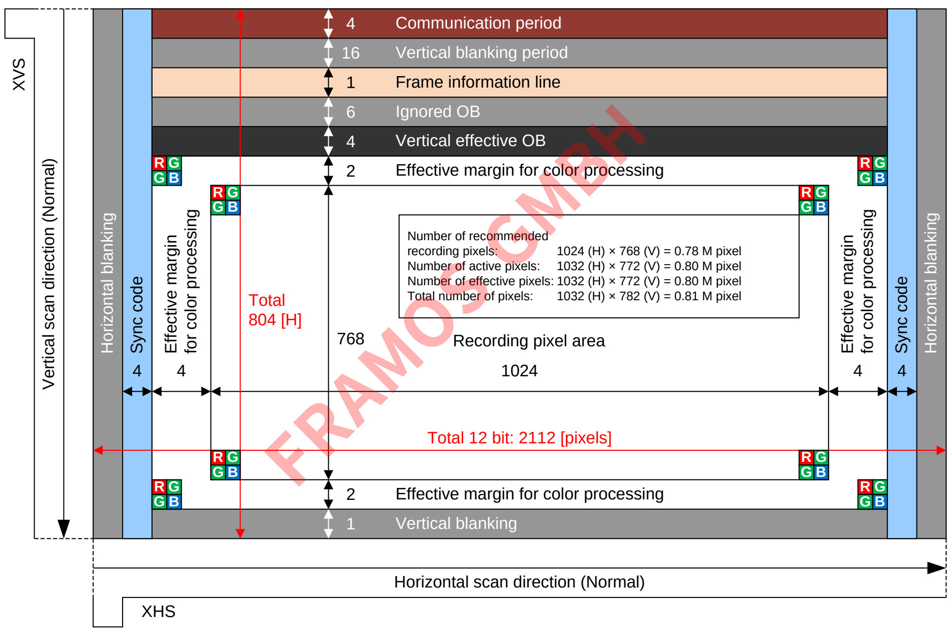
Vertical / Horizontal 1/2 Subsampling mode

V direction and H direction must be set in this mode.

Register List of Vertical / Horizontal 1/2 subsampling mode

Please set All-pixel scan mode to the settings other than the following.

Address	bit	Register name	Initial Value	Setting value AD = 12 bit 116.6 [frame/s]	Remarks
Chip ID = 02h					
0Dh	[3:0]	WINMODE	0h	1h	Subsampling mode
0Dh	[4]	HMODE	0	1	Subsampling mode
10h	[7:0]	VMAX	82Eh	324h	804 line
11h	[7:0]				
12h	[3:0]				
14h	[7:0]	HMAX	15Eh	318h	
15h	[7:0]				



Pixel Array Image Drawing in Vertical / Horizontal 1/2 subsampling mode

Description of Various Function

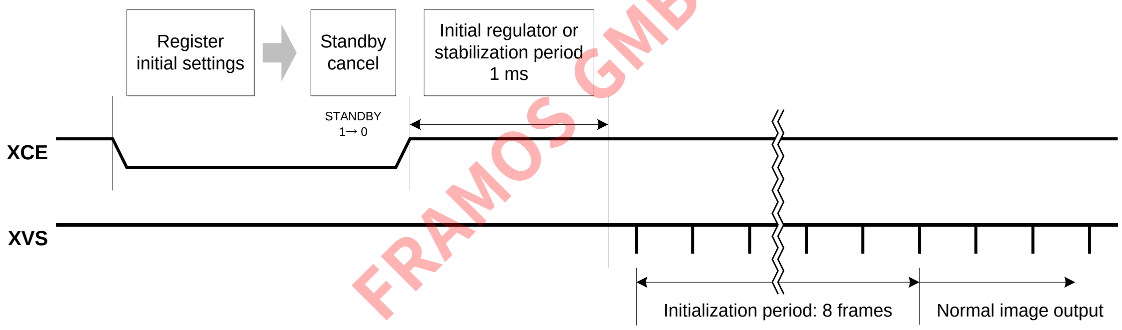
Standby mode

This sensor stops its operation and goes into standby mode which reduces the power consumption by writing “1” to the standby control register STANDBY. Standby mode is also established after power-on or other system reset operation.

Register List of Standby setting

Register	Register details			Initial value	Setting value	Remarks
	Chip ID	Address ( ): I²C	bit			
STANDBY	02h	00h (3000h)	[0]	1h	1h: Standby 0h: Operating	Register communication is executed even in standby mode.

The serial communication registers hold the previous values. However, the address registers transmitted in standby mode are overwritten. The serial communication block operates even in standby mode, so standby mode can be canceled by setting the STANDBY register to “0”. Some time is required for sensor internal circuit stabilization after standby mode is canceled. For details on the sequence of setting and cancel of standby mode, see the sensor setting flow after power on.
After standby mode is canceled, a normal image is output from the 9 frames after internal regulator stabilization (1 ms or more).



Sequence from Standby Cancel to Stable Image Output

Slave Mode and Master Mode

The sensor can be switched between slave mode and master mode.
The switching is made by the XMASTER pin. Establish the XMASTER pin status before canceling the system reset. (Do not switch this pin status during operation.)
Input a vertical sync signal to XVS and input a horizontal sync signal to XHS when a sensor is in slave mode.
For sync signal interval, input data lines to output for vertical sync signal and 1H period designated in each operating mode for horizontal sync signal. See the section of "Readout Drive mode" for the number of output data line and 1H period.
Set the XMSTA register to "0" in order to start the operation after setting to master mode. In addition, set the count number of sync signal in vertical direction by the VMAX [19:0] register and the clock number in horizontal direction by the HMAX [15:0] register. See the description of operation mode for details of the section of "Readout Drive Modes".

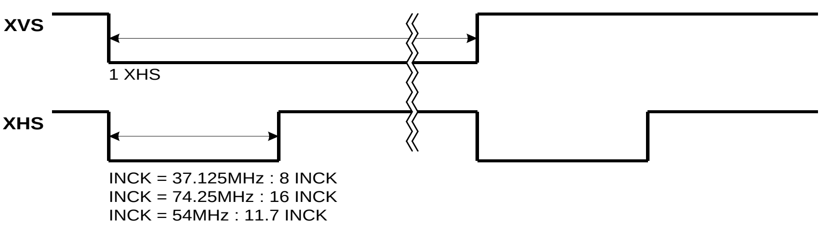
Pin Processing

Pin name	Pin processing	Operation mode	Remarks
XMASTER pin	Low fixed	Master mode	High: OV_{DD} Low: GND
	High fixed	Slave mode	

Register List of Slave Mode and Master Mode

Register	Register details			Initial value	Setting value	Remarks
	Chip ID	Address ( ): I^2C	Bit			
XMSTA	02h	0Ah (300Ah)	[0]	1h	1h: Master operation ready (Initial value) 0h: Master operation start	The master operation starts by setting 0.
VMAX [19:0]		10h (3010h)	[7:0]	0082Eh	See the item of each drive mode	Line number per frame designated (Master mode and Slave mode common setting.)
		11h (3011h)	[7:0]			
		12h (3012h)	[3:0]			
HMAX [15:0]		14h (3014h)	[7:0]	015Eh	See the item of each drive mode	Clock number per line designated (Master mode and Slave mode common setting.)
		15h (3015h)	[7:0]			

XVS / XHS Output Waveform in Master Mode



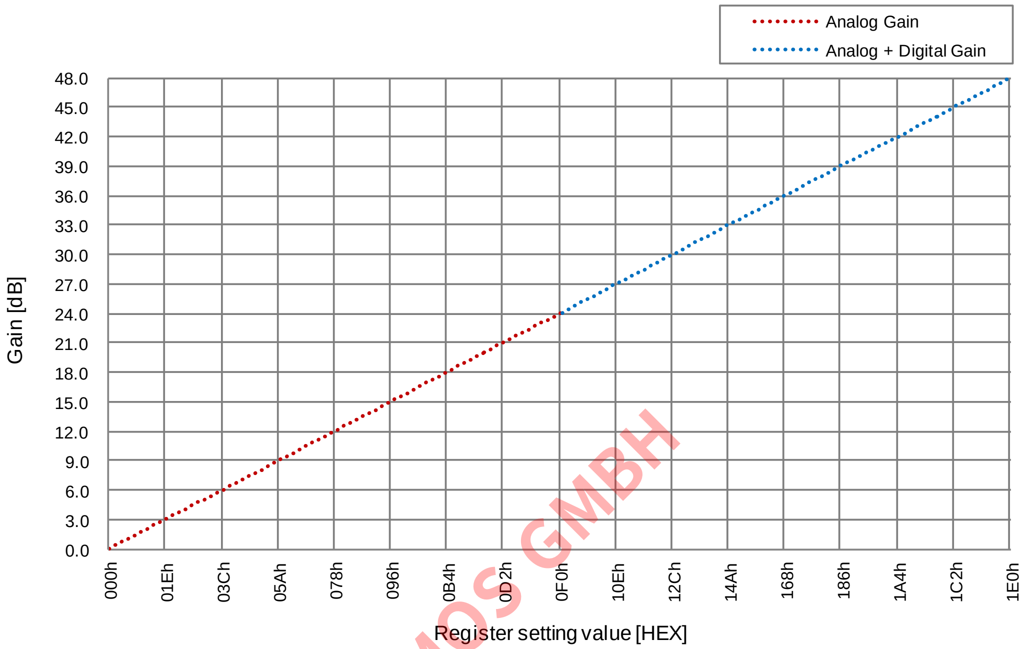
Gain Adjustment Function

PGC

The Programmable Gain Control (PGC) of this device consists of the analog block and digital block.
The total of analog gain and digital gain can be set up to 48 dB by the GAIN [8:0] register setting.
The value which is ten times the gain is set to register.

Example) When set to 6 dB:

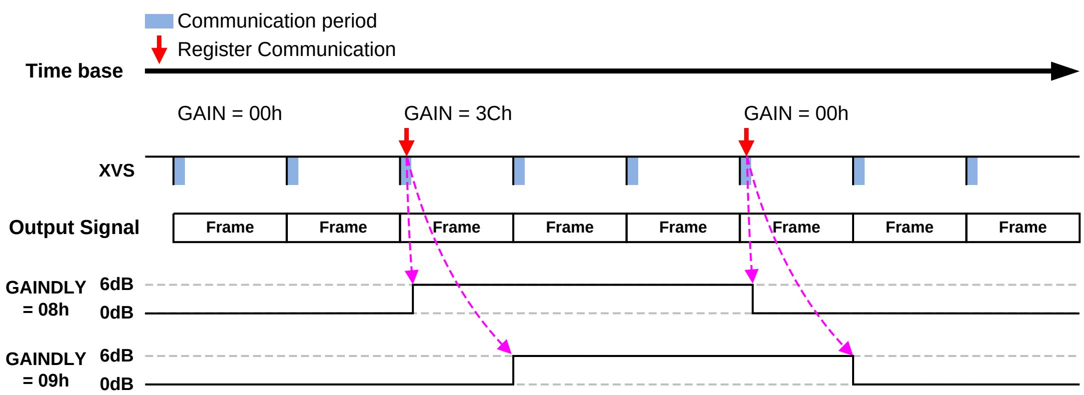
6 × 10 = 60d, GAIN = 03Ch



Register List of Gain setting

<table>
<tr><th rowspan="2">Register</th><th colspan="3">Register details</th><th rowspan="2">Initial value</th><th>Setting value</th><th rowspan="2">Remarks</th></tr>
<tr><th>Chip ID</th><th>Address ( ): I²C</th><th>bit</th><th>Setting range</th></tr>
<tr><td rowspan="2">GAIN [8:0]</td><td rowspan="2">04h</td><td>04h (3204h)</td><td>[7:0]</td><td rowspan="2">000h</td><td rowspan="2">000h to 1E0h (0d to 480d)</td><td rowspan="2">Setting value: Gain [dB] × 10</td></tr>
<tr><td>05h (3205h)</td><td>[0]</td></tr>
</table>

Gain Reflection Timing is changed by the set value of GAINDLY as shown below.



Gain Reflection Timing

Black Level Adjustment Function

The black level offset (offset variable range: 000h to 1FFh) can be added relative to the data in which the digital gain modulation was performed by the BLKLEVEL [11:0] register. When the BLKLEVEL [11:0] setting is increased by 1 LSB, the black level is increased by 1 LSB.

* Use with values shown below is recommended.
12 bit output: 0F0h (240 d)

Register List of Black level adjustment

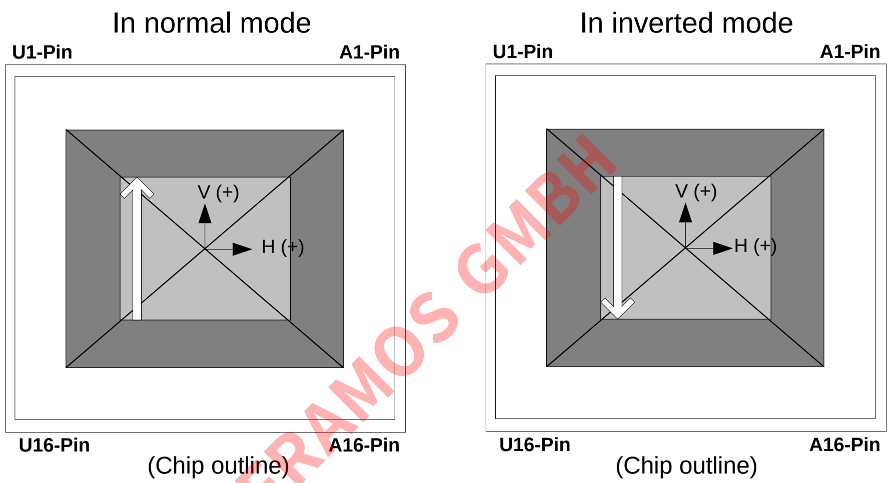
Register	Register details			Initial value	Setting value
	Chip ID	Address ( ): I^2C	bit		
BLKLEVEL [11:0]	04h	54h (3254h)	[7:0]	03Ch	000h to FFFh
		55h (3255h)	[3:0]		

Horizontal / Vertical Normal Operation and Inverted Operation

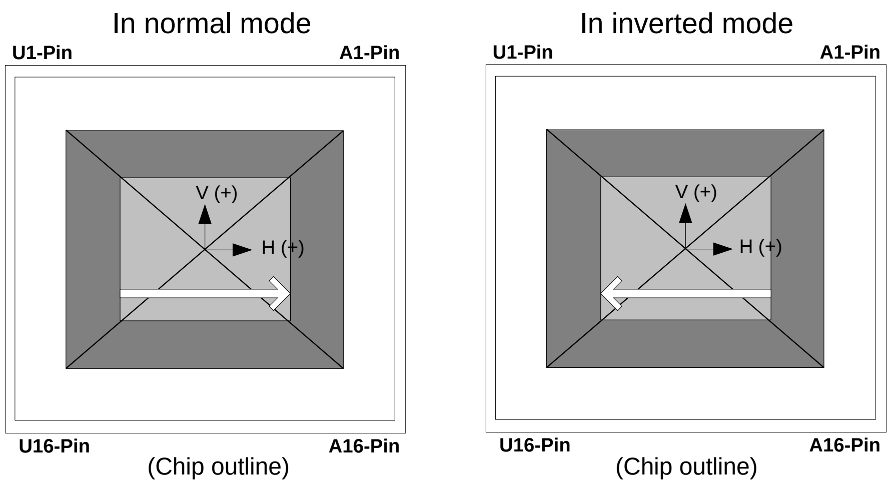
The sensor readout direction (normal / inverted) in vertical direction can be switched by the VREVERSE register setting and sensor readout direction (normal / inverted) in horizontal direction can be switched by the HREVERSE register setting. See the section of “Readout Drive Modes” for the order of readout lines in normal and inverted modes.

Register List of Readout Drive Direction setting

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ): I^2C	bit		
VREVERSE	02h	0Eh (300Eh)	[0]	0h	0h: Normal (Initial value) 1h: Inverted
HREVERSE			[1]	0h	0h: Normal (Initial value) 1h: Inverted



Normal and Inverted Drive Outline in Vertical Direction (TOP VIEW)



Normal and Inverted Drive Outline in Horizontal Direction (TOP VIEW)

Shutter and Integration Time Settings

This sensor has a global shutter function that integrates to all line collectively by using memory in each pixel. This sensor has a variable electronic shutter function that can control the integration time in line units for adjust the exposure time. This sensor transferred signal to memory in pixel after the exposure (memory transfer), then this sensor performs output in which readout operation is performed sequentially for each line in sync with the XHS signal. This sensor has trigger mode that can be controlled exposure start timing and memory transfer timing by trigger.

Note) For integration time control, an image which reflects the setting is output from the frame after the setting changes.

In this item, the shutter operation and storage time are shown as in the figure below with the time sequence on the horizontal axis and the vertical address on the vertical axis. For simplification, shutter and readout operation are noted in line units.

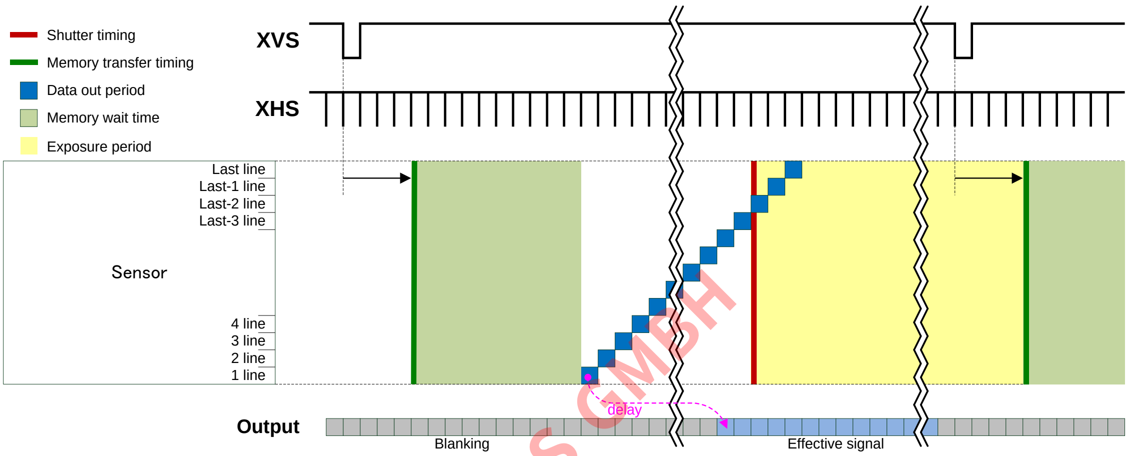


Image Drawing of Global Shutter (Normal mode) Operation

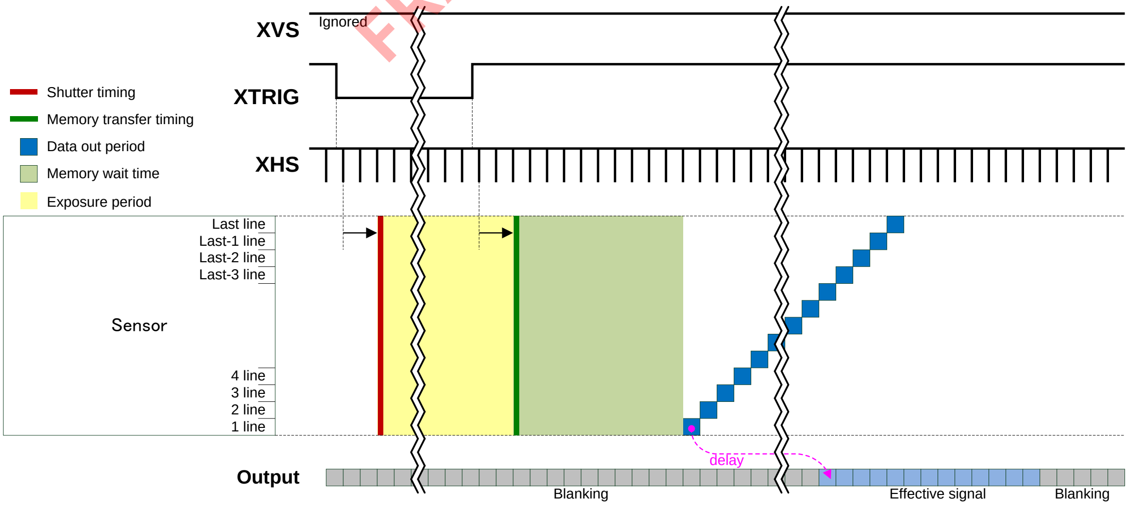


Image Drawing of Global Shutter (Sequential Trigger mode) Operation

Global Shutter (Normal Mode) Operation

The integration time can be controlled by varying the electronic shutter timing. In the electronic shutter settings, the integration time is controlled by the SHS [19:0] register. For setting value of SHS [19:0], see the table “List of Exposure Setting”. When the sensor is operating in slave mode, the number of lines per frame is determined by the XVS interval (number of lines), using the input XHS interval as the line unit. When the sensor is operating in master mode, the number of lines per frame is determined by the VMAX [19:0] register. The number of lines per frame differs according to the operating mode.

Calculation Formula of Exposure Time

Exposure time [s] = (1 H period) × (Number of lines per frame - SHS) + 13.73 [μs][*1]
[*1]: Exposure time error (t_{OFFSET})

Register List of Shutter setting

<table>
<tr><th rowspan="2">Register</th><th colspan="3">Register details</th><th rowspan="2">Initial value</th><th rowspan="2">Setting value</th></tr>
<tr><th>Chip ID</th><th>Address
( ): I²C</th><th>bit</th></tr>
<tr><td rowspan="3">VMAX [19:0]</td><td rowspan="6">02h</td><td>10h
(3010h)</td><td>[7:0]</td><td rowspan="3">0082Eh</td><td rowspan="3">Set the number of lines per frame (only in master mode)</td></tr>
<tr><td>11h
(3011h)</td><td>[7:0]</td></tr>
<tr><td>12h
(3012h)</td><td>[3:0]</td></tr>
<tr><td rowspan="3">SHS [19:0]</td><td>8Dh
(308Dh)</td><td>[7:0]</td><td rowspan="3">0000Ah</td><td rowspan="3">Sets the shutter sweep time.
memory wait time to (Number of lines per frame - 1)</td></tr>
<tr><td>8Eh
(308Eh)</td><td>[7:0]</td></tr>
<tr><td>8Fh
(308Fh)</td><td>[3:0]</td></tr>
</table>

List of Exposure Setting

Drive mode	memory wait time [H]	Number of lines per frame [DEC]	SHS Setting value [DEC]	Exposure Setting value [H]	4 ch LVDS / Maximum frame rate	
					Frame rate [frame/s]	Actually exposure [ms][*4]
					12 bit	12 bit
All-pixel	8	1576	1575	1	55.6	0.025
			1574	2		0.037
			…	…		…
			9	1567		17.868
			8	1568		17.879
1080p-Full HD	6	1125	1124	1	60	0.029
			1123	2		0.043
			…	…		…
			7	1118		16.577
			6	1119		16.592
ROI	8	V_{TR}[*1]	V_{TR}-1	1	*2	0.025
			V_{TR}-2	2		0.037
			…	…		…
			9	V_{TR}-9		*3
			8	V_{TR}-8		

*1 V_{TR} = ROIWV1 + 32
*2 For the frame rate, see the section “ROI mode” in “Readout Drive Mode”.
*3 Conform to the calculation formula of exposure time. (Number of lines per frame = V_{TR})
*4 INCK frequency is input by typical value, and t_{OFFSET} (13.73 [μs]) is included.

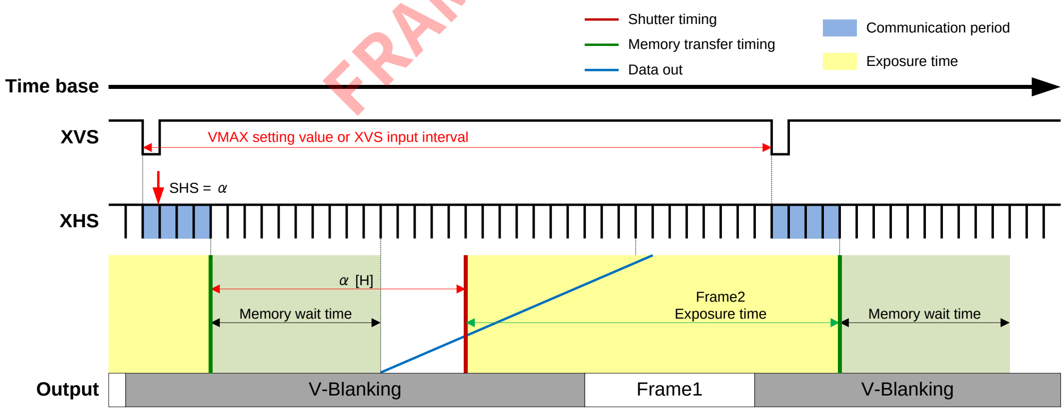


Image Drawing of Global Shutter (Normal Mode)

Global Shutter (Sequential Trigger Mode) Operation

The integration time can be controlled by varying the pulse width that is input to XTRIG pin. The pulse width designated in XHS unit [H]. For the transition from normal mode to trigger mode, set 1 to the register TRIGEN. The XVS input signal is ignored during trigger mode operating. In case of inputting trigger continuously, there are period which prohibit the trigger rise input (t_{TGPD}) and fall input (t_{GES}) based on the previous trigger rise.
When the trigger rise is input before the rise input prohibited period (t_{TGPD}), interrupt operation starts.
This function is slave mode only. The number of lines per frame differs according to the operating mode.

Calculation Formula of Exposure Time

Exposure time [s] = (XTRIG low level pulse width [H][*2]) + 13.73 [µs][*1]
[*1]: Exposure time error (t_{OFFSET})
[*2]: Low level pulse width is counted by XHS pulse.

Register List of shutter setting

Register	Register details: Chip ID	Address ( ): I²C Address	bit	Initial value	Setting value
XMSTA	02h	0Ah (300Ah)	[0]	1h	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop
TRIGEN	02h	0Bh (300Bh)	[0]	0h	0h: Global shutter (normal mode) 1h: Global shutter (trigger mode)
VINT_EN	02h	AAh (30AAh)	[0]	1h	Setting of Interrupt mode in Trigger Mode 0: V interrupt is disable 1: V interrupt is enable

Parameter List of Global Shutter (Sequential Trigger Mode)

Item	Symbol	Min.	Typ.	Max.	Unit
Integration start delay	t_{TGST}	2	—	3	H
Integration end delay	t_{TGED}	2 + t_{OFFSET}	—	3 + t_{OFFSET}	H
Integration time	t_{TGSE}	1	—	—	H
Next trigger fall prohibited period (All-pixel, ROI, 1/2 Subsampling)	t_{TGES}	11	—	—	H
Next trigger fall prohibited period (1080p Full-HD)		9	—	—	H
Next trigger rise prohibited period (All-pixel)	t_{TGPD}	1580	—	—	H
Next trigger rise prohibited period (1/2 Subsampling)		808			
Next trigger rise prohibited period (1080p Full-HD)		1125	—	—	
Next trigger rise prohibited period (ROI)		V_{TR} [*1]	—	—	
Data output delay (All-pixel / ROI)	t_{TGDLY}	—	19	—	H
Data output delay (1080p-Full HD)		—	15	—	

[*1] V_{TR} = ROIWV1 + 32

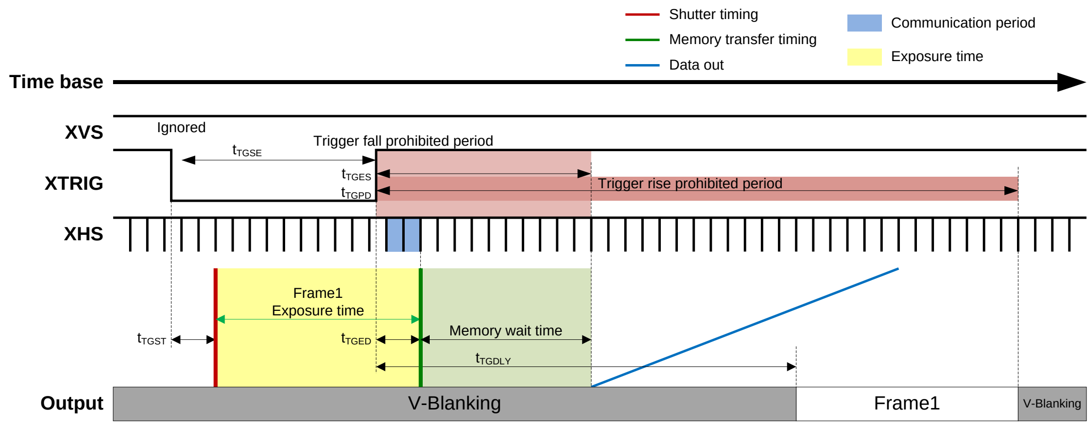


Image Drawing of Global Shutter (Sequential Trigger Mode)

Interrupt Operation

In case of VINT_EN = 1h, the image drawing when the interrupt operation is generated is shown below. When the trigger is raised again and the next frame is output during read of the frame for which read was started by a trigger rise (Frame 1 in the figure below), Frame 1 becomes an invalid frame. Trigger timing of interrupt generating corresponds to t_{TGPD} in Parameter List of Global Shutter (Trigger Mode)
In case of VINT_EN = 0h, the trigger signal is ignored in t_{TGPD} (Prohibit period).
But in case of VINT_EN = 0h, the rising edge of the trigger signal which is input during GSDLY (CID = 02h, Address = A0h) + 5H before the end of read out isn't ignored.
*This is not applicable to the falling edge of the trigger signal.

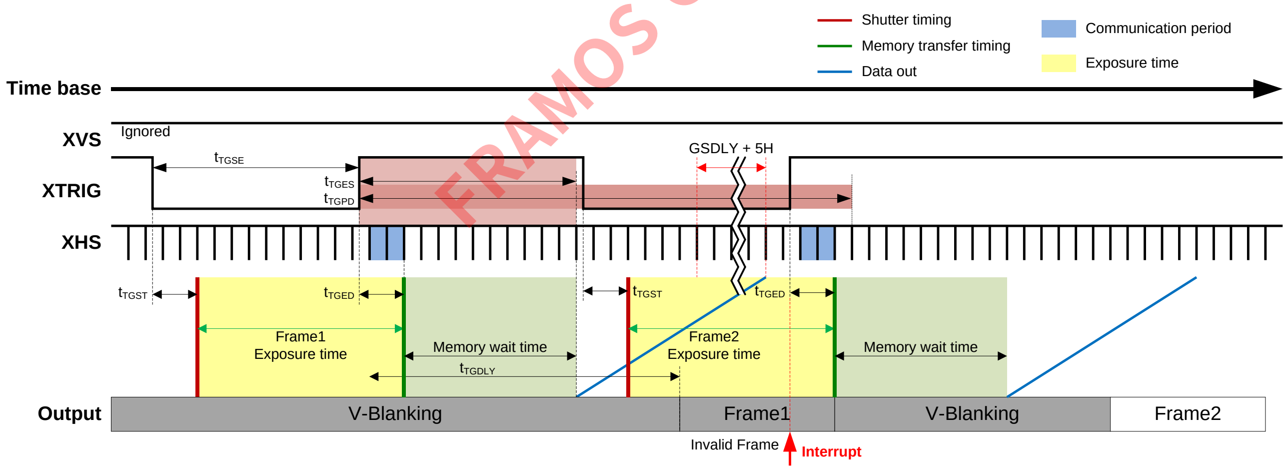


Image Drawing of Interrupt Operation in Global Shutter (Sequential Trigger Mode)

Global Shutter (Fast Trigger Mode) Operation

Fast trigger mode is the trigger mode that starts exposure at fall of XTRIG immediately.
This mode supports Master mode only.

Calculation Formula of Exposure Time

Exposure time [s] = (XTRIG low level pulse width [μs]) + 13.73 [μs][*1]
[*1]: Exposure time error (t_{OFFSET})

Register List of shutter setting

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ): I²C Address	bit		
XMSTA	02h	0Ah (300Ah)	[0]	1h	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop
TRIGEN		0Bh (300Bh)	[0]	0h	0h: Global shutter (normal mode) 1h: Global shutter (trigger mode)
SYNCSEL		36h (3036h)	[5:4]	0h	XHS, XVS pin setting 0h: Normal Output 3h: Hi-Z
LOWLAGTRG		AEh (30AEh)	[0]	0h	Selection of trigger mode 0: Sequential trigger mode 1: Fast trigger mode

Parameter List of Global Shutter (Fast Trigger Mode)

Item	Symbol	Min.	Typ.	Max.	Unit
Integration start delay	t_{TGST}	—	—	0.05	μs
Trigger width	t_{TGED}	—	—	0.05 + t_{OFFSET}	μs
Integration time	t_{TGSE}	0.05	—	—	μs
Next trigger rise / fall prohibited period (All-pixel)	t_{TGPD}	1596	—	—	H
Next trigger rise / fall prohibited period (1/2 Subsampling)		824			
Next trigger rise / fall prohibited period (1080p Full-HD)		1141	—	—	
Next trigger rise / fall prohibited period (ROI)		V_{TR} [*1]	—	—	
Data output delay (All-pixel / ROI)	t_{TGDLY}	—	19	—	H
Data output delay (1080p-Full HD)		—	15	—	

[*1] V_{TR} = ROIWV1 + 32

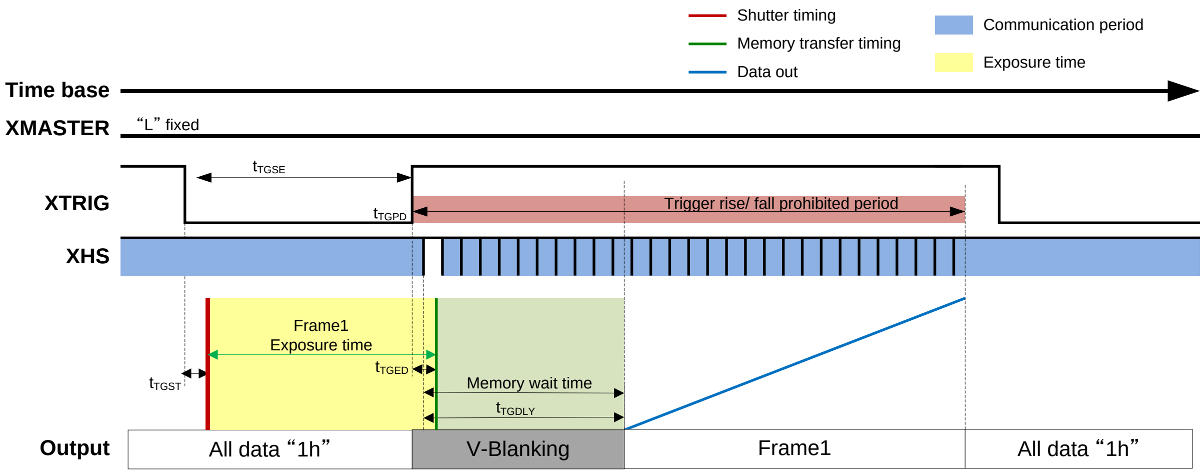


Image Drawing of Global Shutter (Fast Trigger Mode) (4-wire)

Mode Transitions of Global Shutter Operation

The sensor can be switched between normal mode and trigger mode in global shutter operation by setting the register TRIGEN. The sensor will transition to normal mode or trigger mode 20H after the register TRIGEN is set. (The XVS and XTRIG input during transition are prohibited.)
In case of Fast Trigger mode, the mode transition must be done via sensor standby.

Transition from Normal Mode to Sequential Trigger Mode

The sensor will transition from normal mode to trigger mode after setting 1d to register TRIGEN. The XVS input is ignored after transition to trigger mode. Trigger input is prohibited for a 20H period after the register TRIGEN is set. When TRIGEN is set during data read, read operation is stopped and that frame becomes an invalid frame.
* The communication is available till 9 H period only when sensor transition to the Trigger mode.

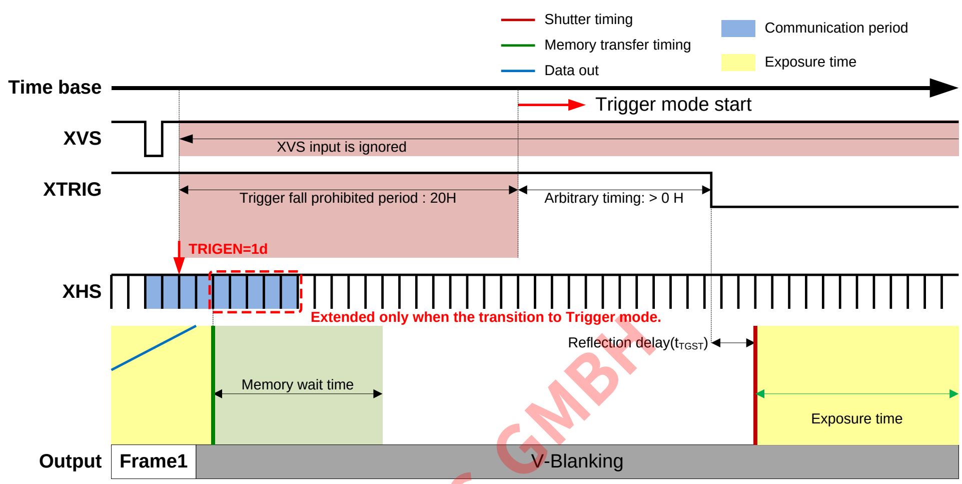


Image Drawing of Transition from Normal Mode to Sequential Trigger Mode

Transition from Sequential Trigger Mode to Normal Mode

The sensor will transition from trigger mode to normal mode after setting 0d to register TRIGEN. Start XVS input after transition to normal mode. Set TRIGEN after Next trigger rise prohibited period (t_{TGPD}) has passed. When TRIGEN is set before t_{TGPD}, read operation is stopped and that frame becomes an invalid frame.

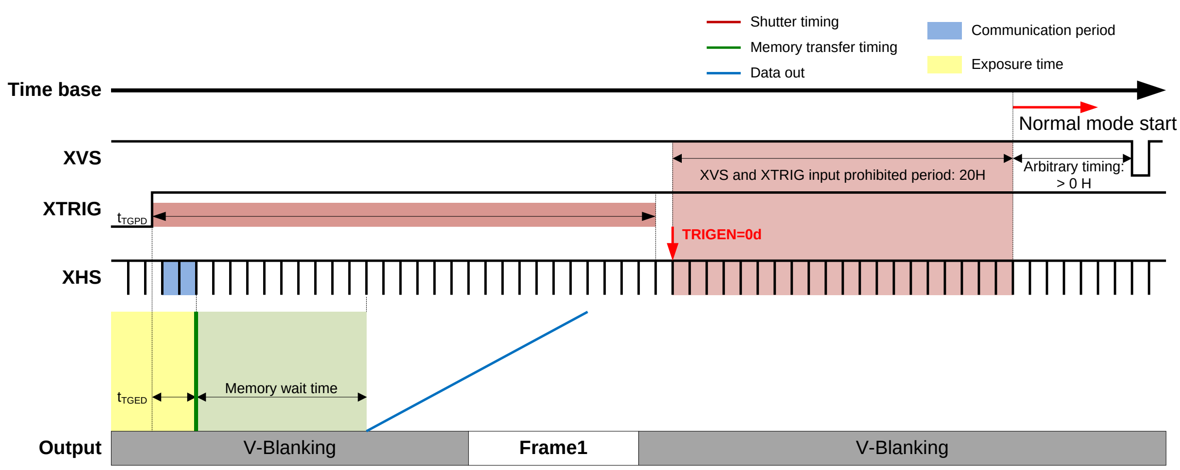


Image Drawing of Transition from Sequential Trigger Mode to Normal Mode

Pulse Output Function

This sensor has a pulse output function that indicates each state of shutter operation. The pulse output from TOUT1 pin and TOUT2 pin. The rise timing and fall timing of pulse are set by Register. For the reference point (The timing when register value set to 0) to be set, see the table “List of Reference point". The pulse is output asynchronously with other signals on the basis of the sensor internal timing shown in the “List of Reference point". This function doesn't support Fast Trigger mode.

Register List of Pulse Output Function

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ): I^2C	bit		
TOUT1SEL [1:0]	02h	26h (3026h)	[1:0]	0h	TOUT1 pin setting 0h: Low fixed 3h: Pulse output
TOUT2SEL [1:0]			[3:2]	0h	TOUT2 pin setting 0h: Low fixed 3h: Pulse output
TRIG_TOUT1_SEL [2:0]		29h (3029h)	[2:0]	0h	TOUT1 pin output selection 0h: Low fixed 1h: Pulse1 output
TRIG_TOUT2_SEL [2:0]			[6:4]	0h	TOUT2 pin output selection 0h: Low fixed 2h: Pulse2 output
PULSE1_EN_NOR		6Dh (306Dh)	[0]	0	Pulse1 enable in normal mode 0: disable 1: enable
PULSE1_EN_TRIG			[1]	0	Pulse1 enable in trigger mode 0: disable 1: enable
PULSE1_POL			[2]	0	Pulse1 polarity selection 0: High active 1: Low active
PULSE1_UP [19:0]		70h (3070h)	[7:0]	00000h	Pulse1 active period start timing setting Designated in line units from reference point
		71h (3071h)	[7:0]		
		72h (3072h)	[3:0]		
PULSE1_DN [19:0]		74h (3074h)	[7:0]	00000h	Pulse1 active period end timing setting Designated in line units from reference point
		75h (3075h)	[7:0]		
		76h (3076h)	[3:0]		
PULSE2_EN_NOR		79h (3079h)	[0]	0	Pulse2 enable in normal mode 0: disable 1: enable
PULSE2_EN_TRIG			[1]	0	Pulse2 enable in trigger mode 0: disable 1: enable
PULSE2_POL			[2]	0	Pulse2 polarity selection 0: High active 1: Low active
			[3]	0	Fixed to1
PULSE2_UP [19:0]		7Ch (307Ch)	[7:0]	00000h	Pulse2 active period start timing setting Designated in line units from reference point
		7Dh (307Dh)	[7:0]		
		7Eh (307Eh)	[3:0]		
PULSE2_DN [19:0]		80h (3080h)	[7:0]	00000h	Pulse2 active period end timing setting Designated in line units from reference point
		81h (3081h)	[7:0]		
		82h (3082h)	[3:0]		

List of Reference Point

	Normal mode	Trigger mode
Reference point of Pulse1	XVS fall edge in N frame	Fall edge of input trigger
Reference point of Pulse2	XVS fall edge in N +1 frame	Rise edge of input trigger

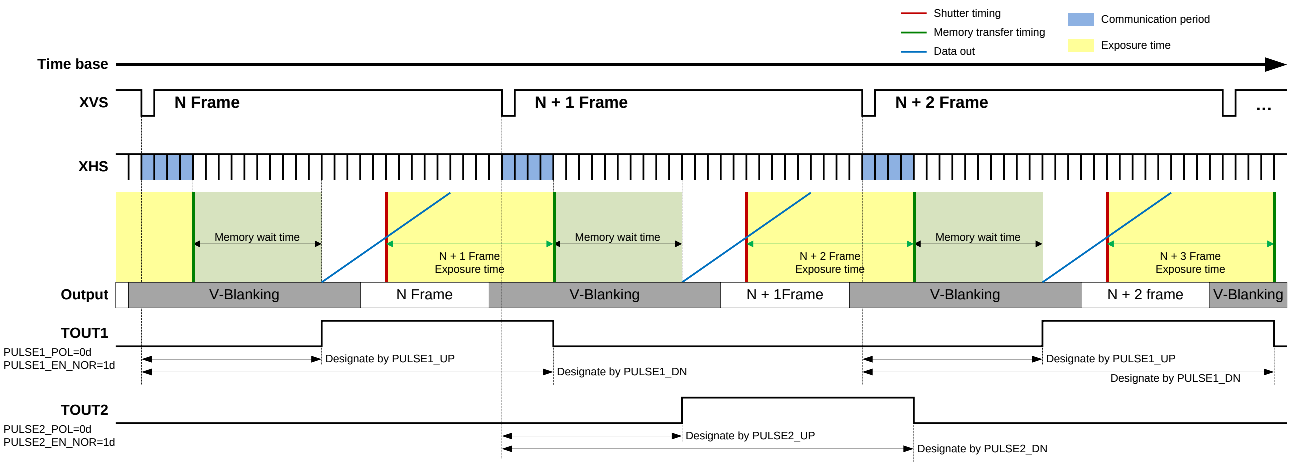


Image Drawing of Pulse Output Function in Global Shutter (Normal Mode)

In normal mode, TOUT1 and TOUT2 are output alternately each time inputting XVS.

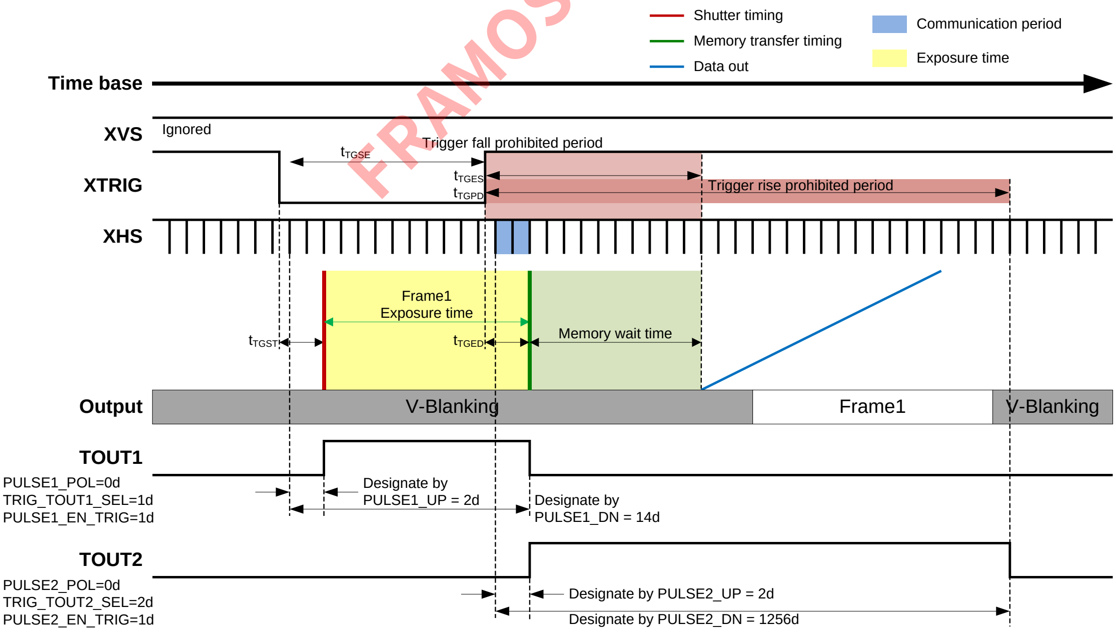


Image Drawing of Pulse Output Function in Global Shutter (Sequential Trigger Mode)

Signal Output

Output Pins

This sensor supports Low voltage LVDS serial (4 ch) DDR output.

Output Pins for Low Voltage LVDS Serial

Output pins	Low voltage LVDS serial DDR output
	4 ch
DLOPC1 / DLOMC1	Ch 3
DLOPD1 / DLOMD1	Ch 1
DLOPE1 / DLOME1	Ch 2
DLOPF1 / DLOMF1	Ch 4
DLCKP1 / DLCKM1	DCK1

Low-voltage LVDS serial 4 ch output format is shown in the figure below.

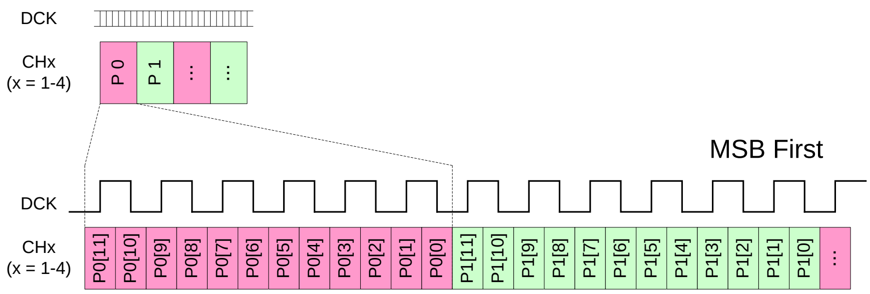
When setting 4 ch after four data of SAV is output in the order of CH1 to CH4 pixel data is repeatedly output in the same order and then four data of EAV is output in the same order to CH1 to CH4 respectively.

Data is sent MSB first. For details, see drive timing in each mode in the section of "Readout Drive Mode".

Output Format of Low voltage LVDS Serial 4 ch

Output Pin Bit Width

Sync code is output according to bit width.



Example of Data format in low-voltage LVDS serial 12-bit output

Output Signal Range

The sensor output has 12-bit gradation, but output is not performed over the full range, and the maximum output value is the “FFFh - 1” (12-bit output). The minimum value is 001h. The output range for each output gradation is shown in the table below. The maximum level and the minimum level are output only in the sync code. See the item of “Sync Codes” in the section of “Operating Modes” for the sync codes.

Output Gradation and Output Range

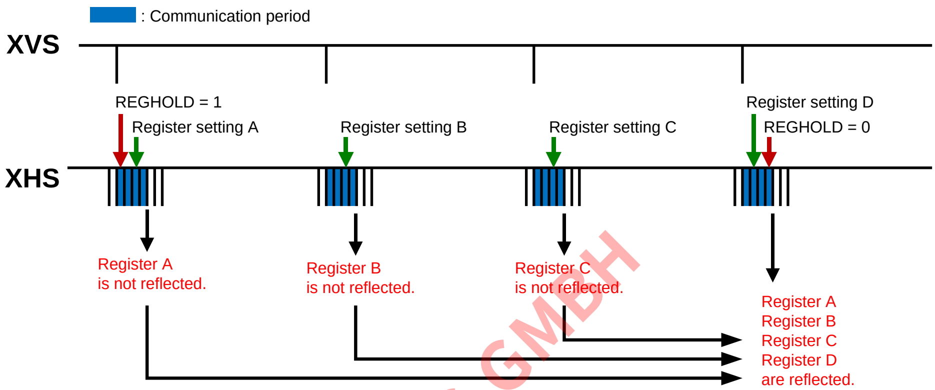
Output gradation	Output value	
	Min.	Max.
12 bit	001h	FFEh

Register Hold Setting

Register setting can be transmitted with divided to several frames and it can be reflected globally at a certain frame by the register REGHOLD. Setting REGHOLD = 1 at the start of register communication period prevents the registers that are set thereafter from reflecting at the frame reflection timing. The registers that are set when setting REGHOLD = 1 are reflected globally by setting REGHOLD = 0 at the end of communication period of the desired frame to reflect the register.

Register List of Register Hold

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ): I^2C	bit		
REGHOLD	02h	08h (3008h)	[0]	0h	0h: Invalid 1h: Valid (Register hold)



Register Hold Setting

Mode Transition

The Mode transition between operations is shown below. These examples shown in case that setting is completed within one communication timing.

List of Mode Transition

Transition			State
ROI	→	All-pixel	Via the Standby state is unnecessary
All-pixel	→	ROI	
- Transition between modes other than the above - Change the input frequency of INCK			Via the standby state is necessary

*1 When changing input INCK frequency, care should be taken not to be input pulses whose width are shorter than the High / Low level width in front and behind of the INCK pulse at the frequency change. If the pulses above generate at the frequency change, change INCK frequency during system reset in the state of XCLR = Low, and then perform system clear in the state of XCLR = High following the item of "Power on sequence" in the section of "Power on / off sequence". Execute initial setting again because the register settings become default state after system clear.

Other Function

This sensor has the function as below. About detail, refer to each application note.

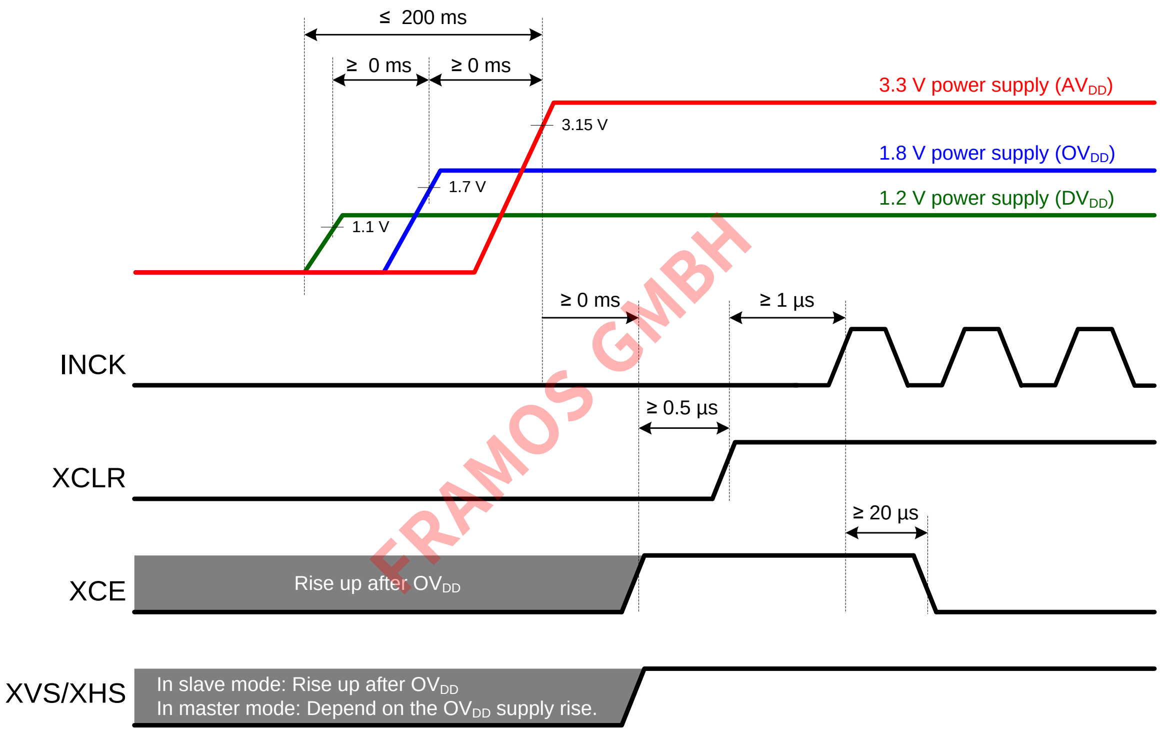
- Multi Frame Set Output mode (2 / 4 frame)
- Multi Exposure Trigger mode
- Driving Low Power Consumption at longtime exposure
- Simple Thermometer
- Gradation Compression
- Pattern Generator

Power-on and Power-off Sequence

Power-on sequence

Follow the sequence below to turn On the power supplies.

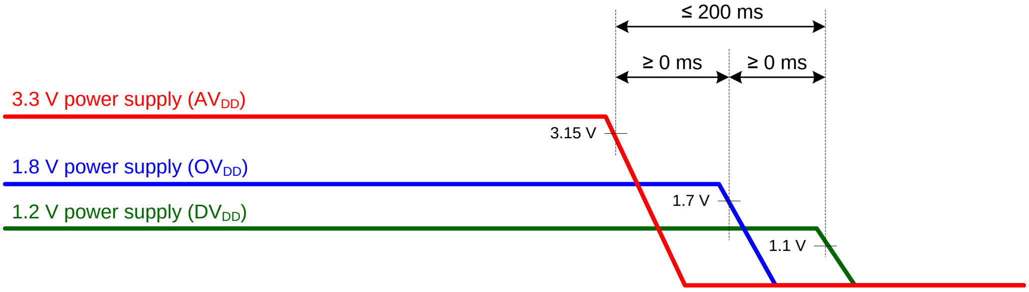
1. Turn On the power supplies so that the power supplies rise in order of 1.2 V power supply (DV_{DD}) →1.8 V power supply (OV_{DD}) → 3.3 V power supply (AV_{DD}). In addition, all power supplies should finish rising within 200 ms.
2. The register values are undefined immediately after power-on, so the system must be cleared. Hold XCLR at Low level for 500 ns or more after all the power supplies have finished rising. (The register values after a system clear are the default values.)
   In addition, hold XCE to High level during this period. Rise XCE after 1.8 V power supply (OV_{DD}), so hold XCE at High level until INCK is input.
3. Start the input of INCK after turning the level of XCLR into the high.
4. Make the sensor setting by register communication after the system clear. A period of 0 µs or more should be provided after setting XCLR High before inputting the communication enable signal XCE.



Power-on Sequence

Power-off Sequence

Turn Off the power supplies so that the power supplies fall in order of 3.3 V power supply (AV_{DD}) → 1.8 V power supply (OV_{DD}) → 1.2 V power supply (DV_{DD}). In addition, all power supplies should finish falling within 200 ms.
Set each digital input pin (INCK, XCE, SCK, SDI, XCLR, XMASTER, XTRIG, SLAMODE, XVS, XHS) to 0 V or high impedance before the 1.8 V power supply (OV_{DD}) falls.

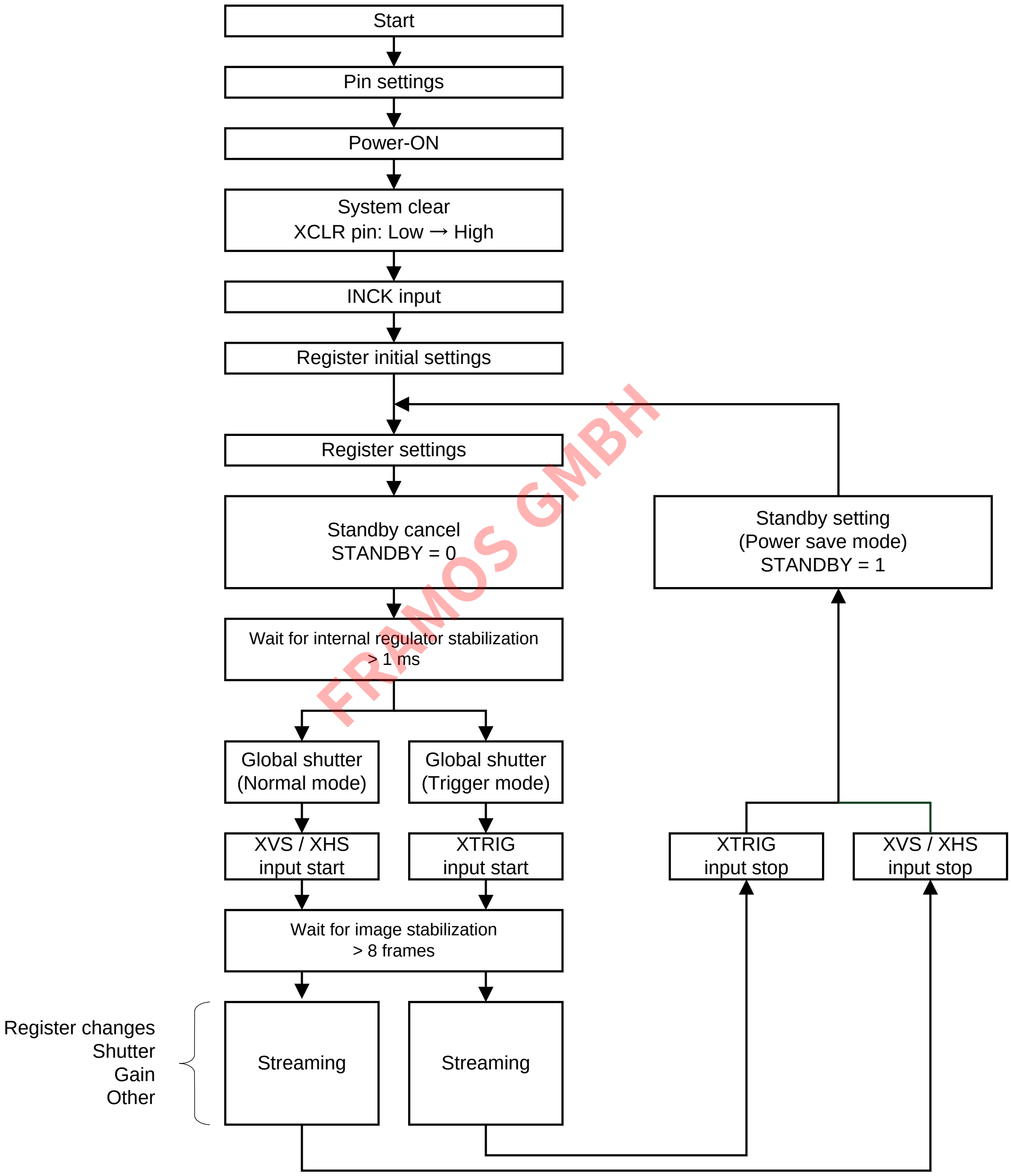


Power-off Sequence

Sensor Setting Flow

Setting Flow in Sensor Slave Mode

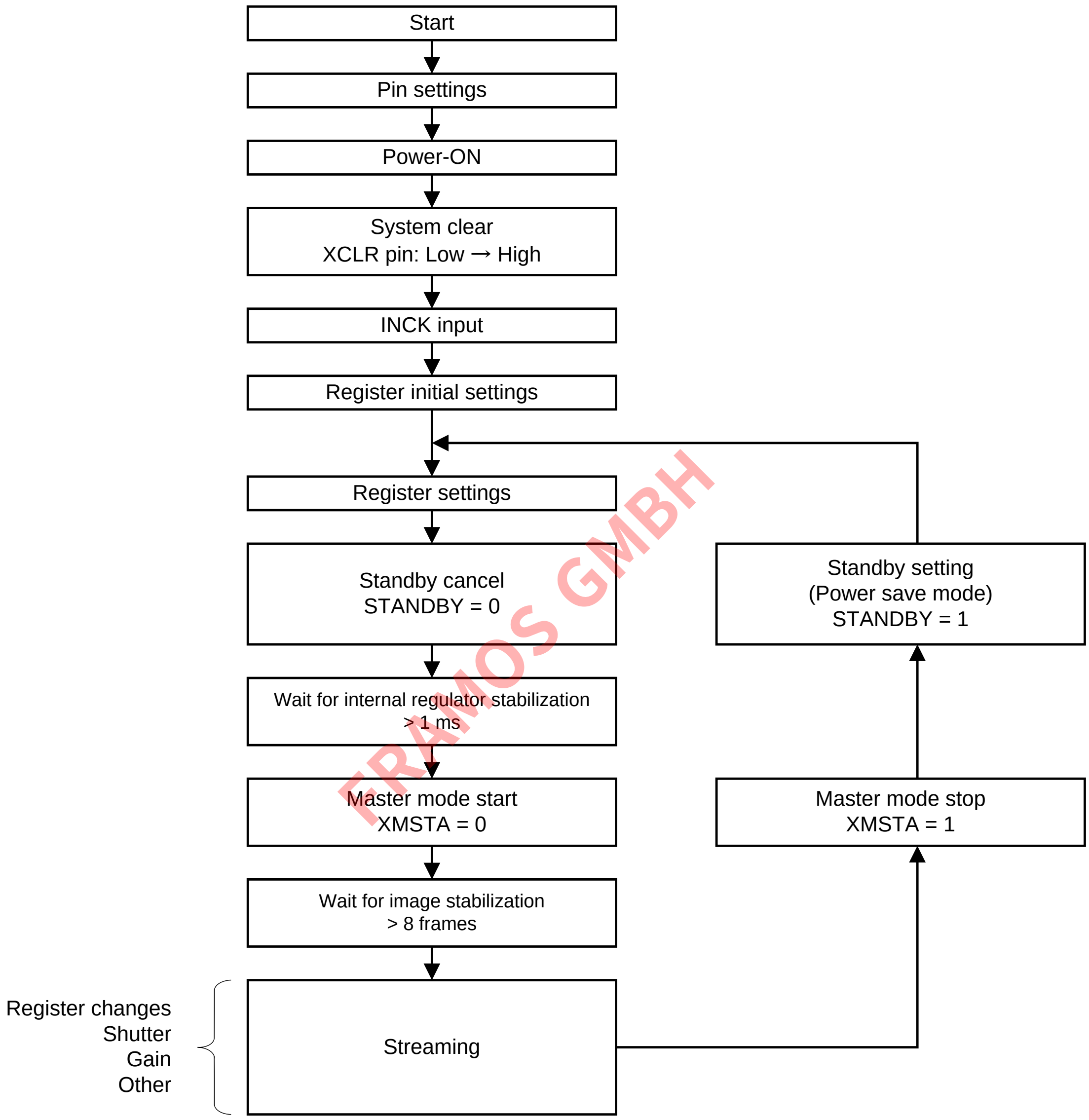
The figure below shows operating flow in sensor slave mode.
For details of "Power on" to "System clear", see the item of "Power on sequence" in this section. For details of "Standby cancel" to "Wait for image stabilization", see the item of "Standby mode". “Standby setting (power save mode) can be made by setting the STANDBY register to “1” during “Operation”.



Sensor Setting Flow (Sensor Slave Mode)

Sensor Flow in Sensor Master Mode

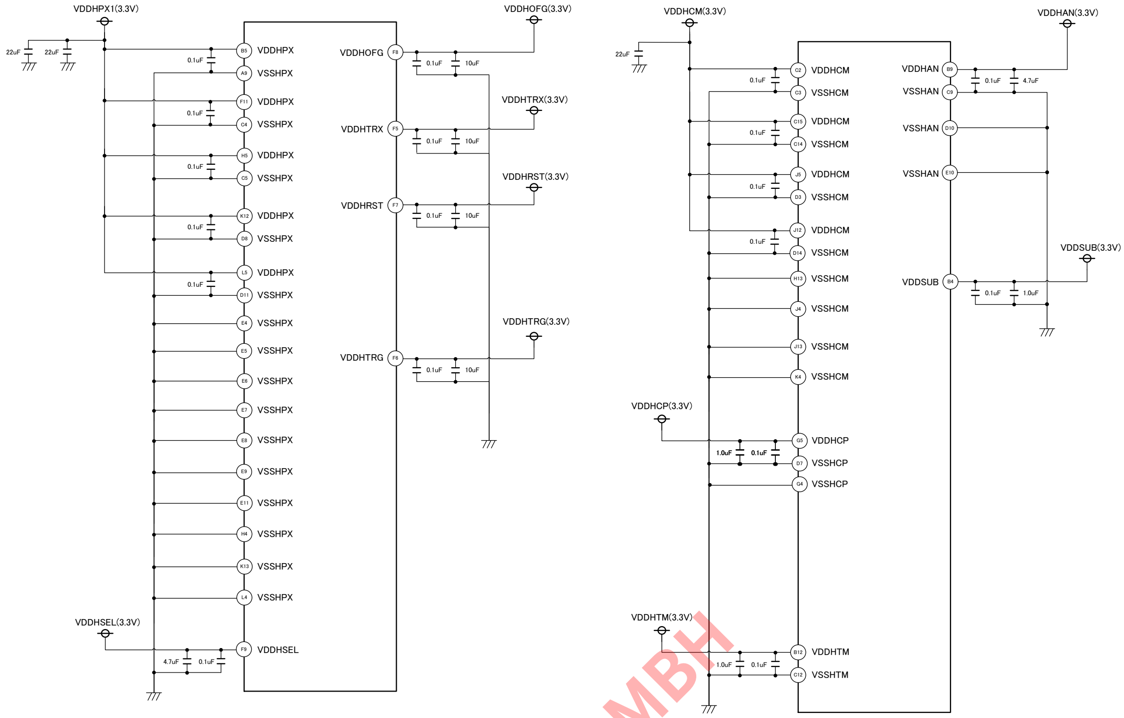
The figure below shows operating flow in sensor master mode.
For details of "Power on" to "System clear", see the item of "Power on sequence" in this section. For details of "Standby cancel" to "Wait for image stabilization", see the item of "Standby mode". In master mode, “Master mode start” by setting the master mode start register XMSTA to “0” after “Wait for internal regulator stabilization”.
“Standby setting (power save mode) can be made by setting the STANDBY register to “1” during “Operation”. This time, set "master mode stop" by setting XMSTA to "1".



Sensor Setting Flow (Sensor Master Mode)

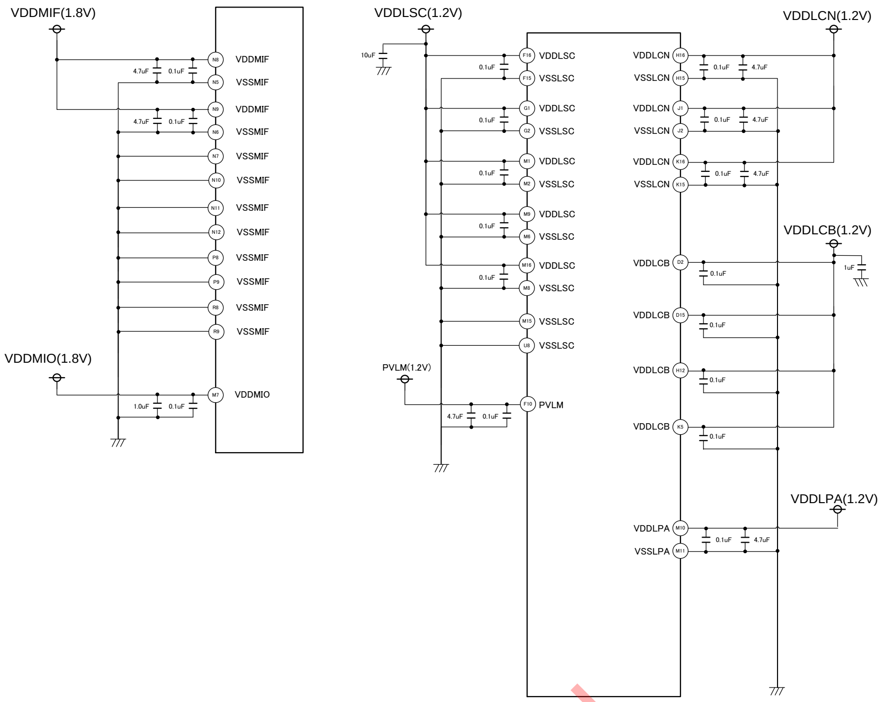
Peripheral Circuit

Analog Power Pins



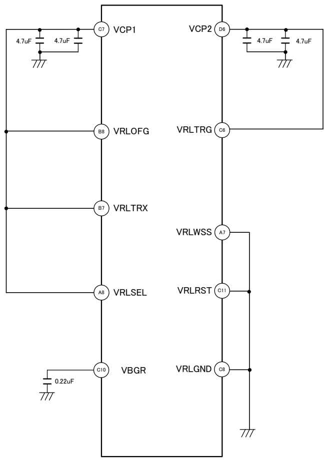
Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

Digital Power Pins



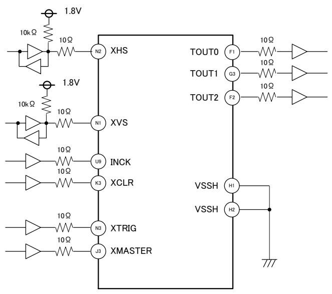
Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

Analog Other Pins

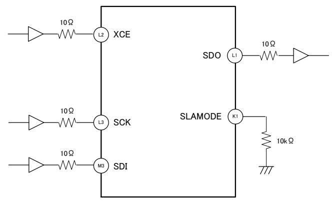


Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

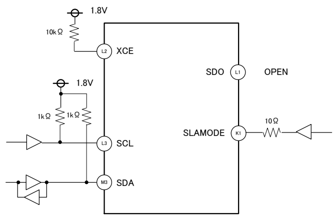
Digital I/O Pins



4-wire serial communication

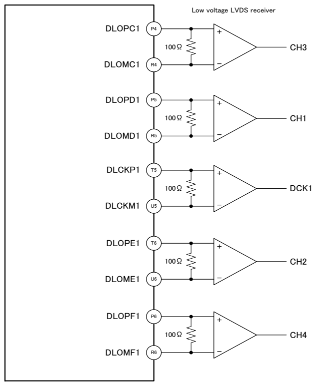


I²C communication



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

Output pins



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

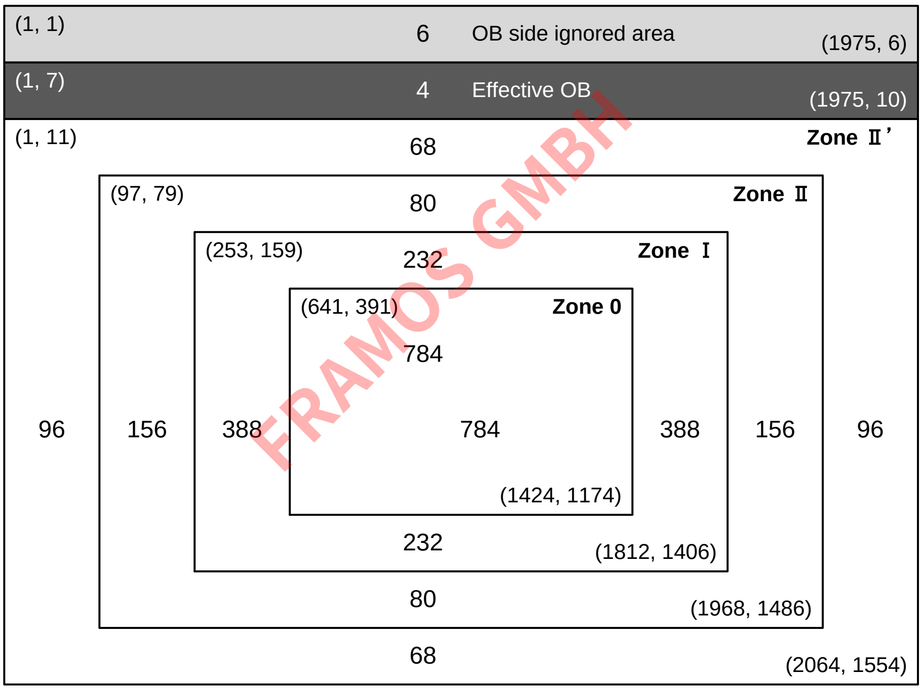
Spot Pixel Specifications

(Tj = 60 ˚C)

Type of distortion	Level	Maximum distorted pixels in each zone			Measurement method	Remarks
		0 to II'	Effective OB	Ineffective OB		
Black and white pixels at high light	30 % ≤ D	24	No evaluation criteria applied		1	
White pixels in the dark	5.6 mV ≤ D	275		No evaluation criteria applied	2	1/30 s storage
Black pixels at signal saturated	D ≤ 700 mV	0	No evaluation criteria applied		3	

Note) 1. Zone is specified based on all-pixel drive mode
2. D…Spot pixel level
3. See the Spot Pixel Pattern Specifications for the specifications in which pixel and black pixel are close.

Sport Pixel Zone Definition



Notice on White Pixels Specifications

After delivery inspection of CMOS image sensors, cosmic radiation may distort pixels of CMOS image sensors, and then distorted pixels may cause white point effects in dark signals in picture images. (Such white point effects shall be hereinafter referred to as "White Pixels".) Unfortunately, it is not possible with current scientific technology for CMOS image sensors to prevent such White Pixels. It is recommended that when you use CMOS image sensors, you should consider taking measures against such White Pixels, such as adoption of automatic compensation systems for White Pixels in dark signals and establishment of quality assurance standards.
Unless the Seller's liability for White Pixels is otherwise set forth in an agreement between you and the Seller, Sony Corporation or its distributors (hereinafter collectively referred to as the "Seller") will, at the Seller's expense, replace such CMOS image sensors, in the event the CMOS image sensors delivered by the Seller are found to be to the Seller's satisfaction, to have over the allowable range of White Pixels as set forth above under the heading "Spot Pixels Specifications", within the period of three months after the delivery date of such CMOS image sensors from the Seller to you; provided that the Seller disclaims and will not assume any liability after you have incorporated such CMOS image sensors into other products.
Please be aware that Seller disclaims and will not assume any liability for (1) CMOS image sensors fabricated, altered or modified after delivery to you, (2) CMOS image sensors incorporated into other products, (3) CMOS image sensors shipped to a third party in any form whatsoever, or (4) CMOS image sensors delivered to you over three months ago. Except the above mentioned replacement by Seller, neither Sony Corporation nor its distributors will assume any liability for White Pixels. Please resolve any problem or trouble arising from or in connection with White Pixels at your costs and expenses.

[For Your Reference] The Annual Number of White Pixels Occurrence

The chart below shows the predictable data on the annual number of White Pixels occurrence in a single-story building in Tokyo at an altitude of 0 meters. It is recommended that you should consider taking measures against the annual White Pixels, such as adoption of automatic compensation systems appropriate for each annual number of White Pixels occurrence.
The data in the chart is based on records of past field tests, and signifies estimated number of White Pixels calculated according to structures and electrical properties of each device. Moreover, the data in the chart is for your reference purpose only, and is not to be used as part of any CMOS image sensor specifications.

Example of Annual Number of Occurrence

White Pixel Level (in case of integration time = 1/30 s) (Tj = 60 °C)	Annual number of occurrence
5.6 mV or higher	7 pcs
10.0 mV or higher	5 pcs
24.0 mV or higher	3 pcs
50.0 mV or higher	2 pcs
72.0 mV or higher	1 pcs

Note 1) The above data indicates the number of White Pixels occurrence when a CMOS image sensor is left for a year.

Note 2) The annual number of White Pixels occurrence fluctuates depending on the CMOS image sensor storage environment (such as altitude, geomagnetic latitude and building structure), time (solar activity effects) and so on. Moreover, there may be statistic errors. Please take notice and understand that this is an example of test data with experiments that have being conducted over a specific time period and in a specific environment.

Note 3) This data does not guarantee the upper limits of the number of White Pixels occurrence.

For Your Reference:

The annual number of White Pixels occurrence at an altitude of 3,000 meters is from 5 to 10 times more than that at an altitude of 0 meters because of the density of the cosmic rays. In addition, in high latitude geographical areas such as London and New York, the density of cosmic rays increases due to a difference in the geomagnetic density, so the annual number of White Pixels occurrence in such areas approximately doubles when compared with that in Tokyo.

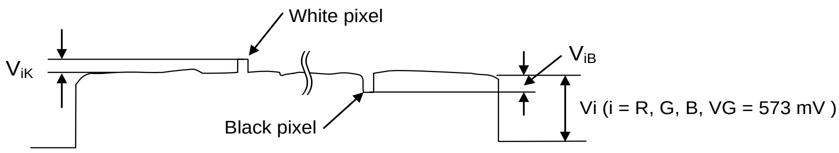
Material_No.03-0.0.8

Measurement Method for Spot Pixels

After setting to standard imaging condition II, and the device driver should be set to meet bias and clock voltage conditions. Configure the drive circuit according to the example and measure.

1. Black or white pixels at high light
   After adjusting the luminous intensity so that the average value V VG of the Gb / Gr signal outputs is 573 mV, measure the local dip point (black pixel at high light, V_{iB}) and peak point (white pixel at high light, V_{iK}) in the Gr / Gb / R / B signal output Vi (i = Gr / Gb / R / B), and substitute the value into the following formula.

   Spot pixel level D = ((V_{iB} or V_{iK}) / Average value of V) × 100 [%]



Signal output waveform of R / G / B channel

2. White pixels in the dark
   Set the device to a dark setting and measure the local peak point of the signal output waveform, using the average value of the dark signal output as a reference.

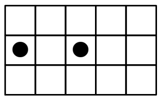
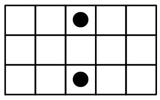
3. Black pixels at signal saturated
   Set the device to operate in saturation and measure the local dip point, using the OB output as a reference.

Signal output waveform

Spot Pixel Pattern Specification

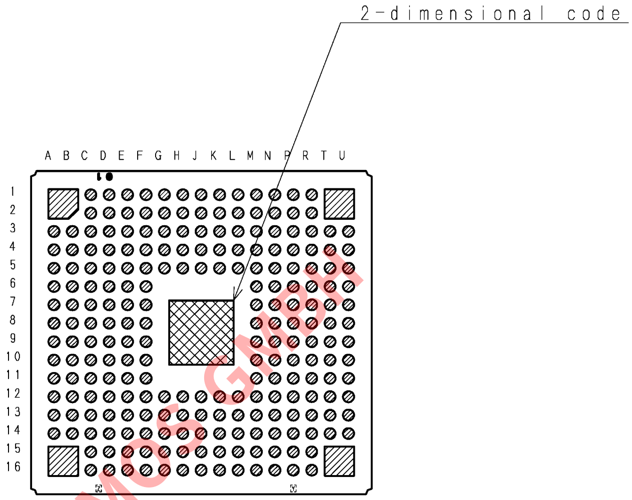
White Pixel, Black Pixel and Bright Pixel are judged from the pattern whether they are allowed or rejected, and counted.

List of White Pixel, Black Pixel and Bright Pixel Pattern

No.	Pattern	White pixel Black pixel Bright pixel
1		Rejected
2		Rejected

Note) 1. "● " shows the position of white pixel, black pixel and bright pixel.
White pixel, black pixel and bright pixel are specified separately according the pattern.
(Example: If a black pixel and a white pixel is in the pattern No.1 respectively, they are not judged to be rejected.)
2. When one or more spot pixels indicated "Rejected" is selected and removed.
3. Spot pixels other than described in the table above are all counted including the number of allowable spot pixels by zone.

Marking



Note: Following characters enter into "Y", and "Z". (No Au coat)
Y: In English upper case character, One character
Z: Number, single number

DRAWING No. AM-A265LQR(2D)

Notes On Handling

1. Static charge prevention

Image sensors are easily damaged by static discharge. Before handling be sure to take the following protective measures.

(1) Either handle bare handed or use non-chargeable gloves, clothes or material.
Also use conductive shoes.
(2) Use a wrist strap when handling directly.
(3) Install grounded conductive mats on the floor and working table to prevent the generation of static electricity.
(4) Ionized air is recommended for discharge when handling image sensors.
(5) For the shipment of mounted boards, use boxes treated for the prevention of static charges.

2. Protection from dust and dirt

Image sensors are packed and delivered with care taken to protect the element glass surfaces from harmful dust and dirt. Clean glass surfaces with the following operations as required before use.

(1) Perform all lens assembly and other work in a clean environment (class 1000 or less).
(2) Do not touch the glass surface with hand and make any object contact with it.
If dust or other is stuck to a glass surface, blow it off with an air blower.
(For dust stuck through static electricity, ionized air is recommended.)
(3) Clean with a cotton swab with ethyl alcohol if grease stained. Be careful not to scratch the glass.
(4) Keep in a dedicated case to protect from dust and dirt. To prevent dew condensation, preheat or precool when moving to a room with great temperature differences.
(5) When a protective tape is applied before shipping, remove the tape applied for electrostatic protection just before use. Do not reuse the tape.

3. Installing (attaching)

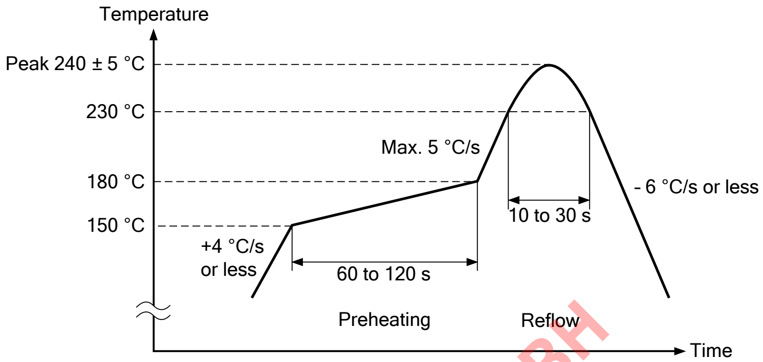
(1) If a load is applied to the entire surface by a hard component, bending stress may be generated and the package may fracture, etc., depending on the flatness of the bottom of the package. Therefore, for installation, use either an elastic load, such as a spring plate, or an adhesive.
(2) The adhesive may cause the marking on the rear surface to disappear.
(3) If metal, etc., clash or rub against the package surface, the package may chip or fragment and generate dust.
(4) Acrylate anaerobic adhesives are generally used to attach this product. In addition, cyanoacrylate instantaneous adhesives are sometimes used jointly with acrylate anaerobic adhesives to hold the product in place until the adhesive completely hardens. (Reference)
(5) Note that the sensor may be damaged when using ultraviolet ray and infrared laser for mounting it.

4. Recommended reflow soldering conditions

The following items should be observed for reflow soldering.

(1) Temperature profile for reflow soldering

Control item	Profile (at part side surface)
1. Preheating	150 to 180 °C 60 to 120 s
2. Temperature up (down)	+4 °C/s or less (- 6 °C/s or less)
3. Reflow temperature	Over 230 °C 10 to 30 s Max. 5 °C/s
4. Peak temperature	Max. 240 ± 5 °C



(2) Reflow conditions

(a) Make sure the temperature of the upper surface of the seal glass resin adhesive portion of the package does not exceed 245 °C.

(b) Perform the reflow soldering only one time.

(c) Finish reflow soldering within 72 h after unsealing the degassed packing.
Store the products under the condition of temperature of 30 °C or less and humidity of 70 % RH or less after unsealing the package.

(d) Perform re-baking only one time under the condition at 125 °C for 24 h.

(3) Others

(a) Carry out evaluation for the solder joint reliability in your company.

(b) After the reflow, the paste residue of protective tape may remain around the seal glass.
(The paste residue of protective tape should be ignored except remarkable one.)

(c) Note that X-ray inspection may damage characteristics of the sensor.

5. Others

(1) Do not expose to strong light (sun rays) for long periods, as the color filters of color devices will be discolored.

(2) Exposure to high temperature or humidity will affect the characteristics. Accordingly avoid storage or use in such conditions.

(3) This product is precision optical parts, so care should be taken not to apply excessive mechanical shocks or force.

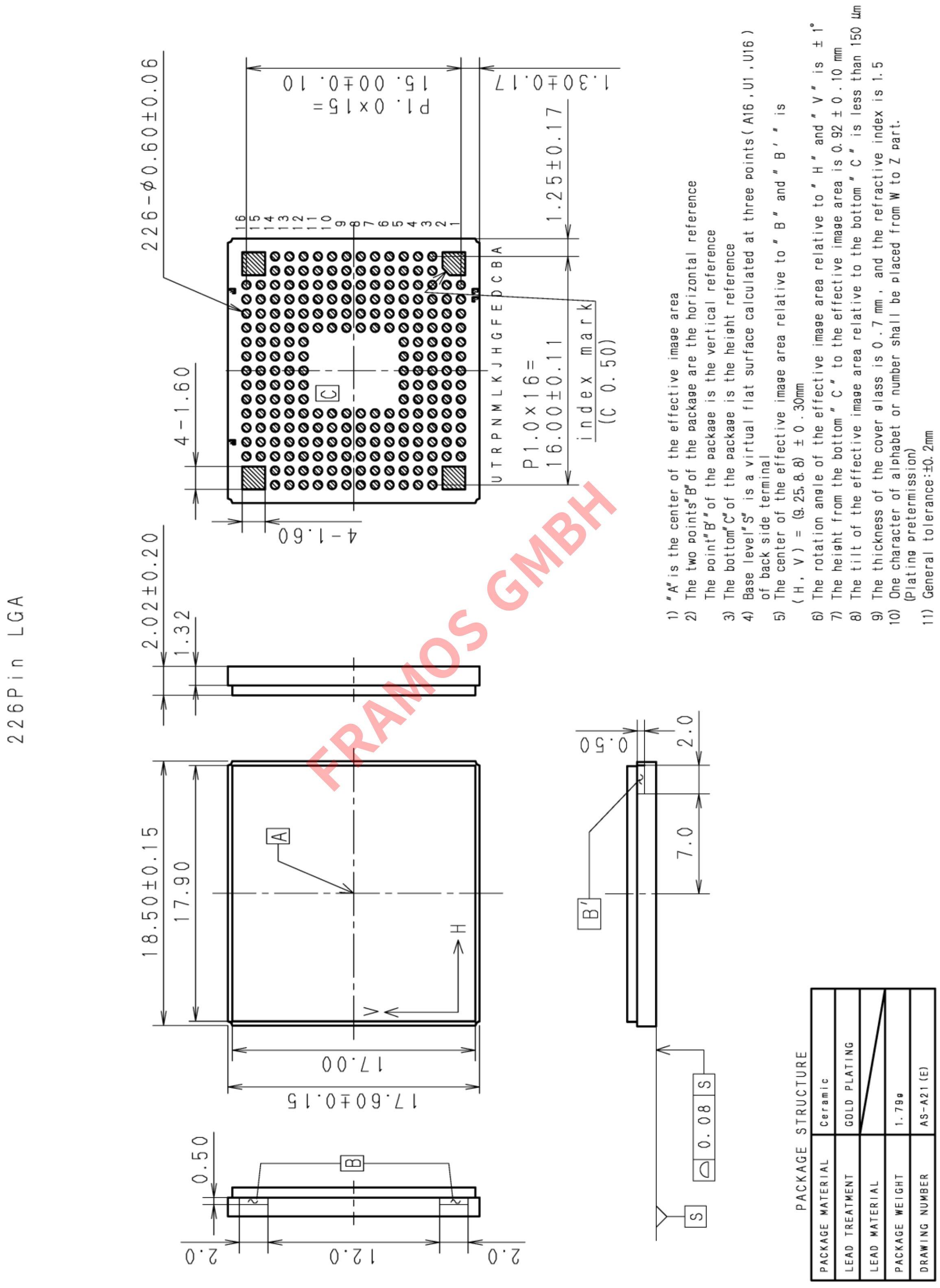
(4) Note that imaging characteristics of the sensor may be affected when approaching strong electromagnetic wave or magnetic field during operation.

(5) Note that image may be affected by the light leaked to optical black when using an infrared cut filter that has transparency in near infrared ray area during shooting subjects with high luminance.

Material_No.14-0.0.6

Package Outline

(Unit: mm)



List of Trademark Logos and Definition Statements

Exmor

* Exmor is a trademark of Sony Corporation. The Exmor is a version of Sony's high performance CMOS image sensor with high-speed processing, low noise and low power dissipation by using column-parallel A/D conversion.

Pregius

* Pregius is a trademark of Sony Corporation. The Pregius is global shutter pixel technology for active pixel-type CMOS image sensors that use Sony's low-noise CCD structure, and realizes high picture quality.

SONY

Revision History

Date of change	Revision	Page	Contain of Change
20-Aug-15	0.1.0	—	First edition (Preliminary version)
16-Oct-15	E15X06	P1	Delete: “Preliminary”
		P7	Update: Optical Center figure.
		P15	Correction: TBD in the chart. (Power Consumption)
		P23	Correction: TBD in the chart. (Image Sensor Characteristics)
		P25	Correction: Number 2 - 5 item in “Measurement Method”.
		P66	Correction: TBD in the chart. (Parameter List of Global Shutter)
		P86	Correction: TBD in the chart. (Annual number of occurrence)
		P87	Correction: TBD in the chart. (Measurement Method for Spot Pixels)
		P89	Update: Marking.
		P92	Update: Package Outline
		—	First edition (Official version)
29-Oct-15	E15X06A5X	P45	Correction: HD1080p deletes “INCK: 54MHz” values in the chart. (HD1080p is outside the support.)